

Overview

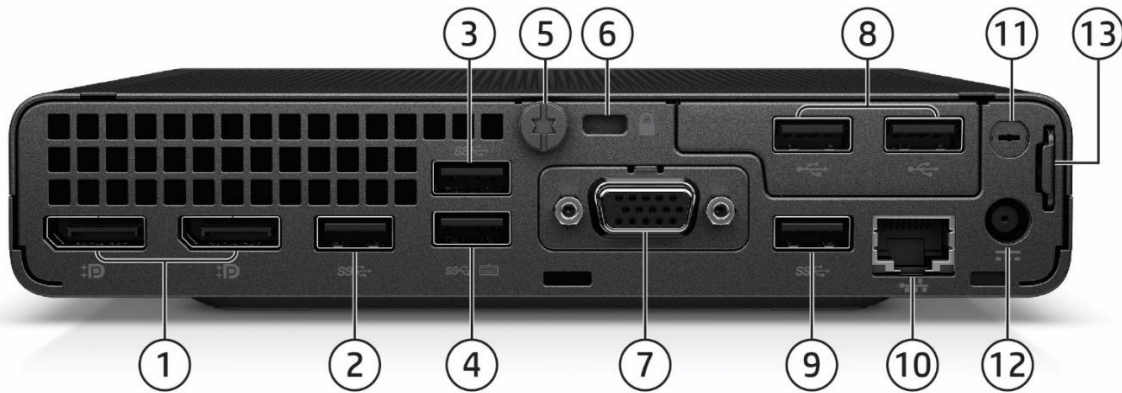
HP EliteDesk 800 G6 Desktop Mini Business PC



1. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
2. Type-A SuperSpeed USB 10Gbps signaling rate port
3. Type-A SuperSpeed USB 5Gbps signaling rate port (charge support up to 5V/2.1A)
4. Combo Audio Jack with CTIA and headset support
5. Dual-state power button
6. Hard drive activity light

Overview

HP EliteDesk 800 G6 Desktop Mini Business PC



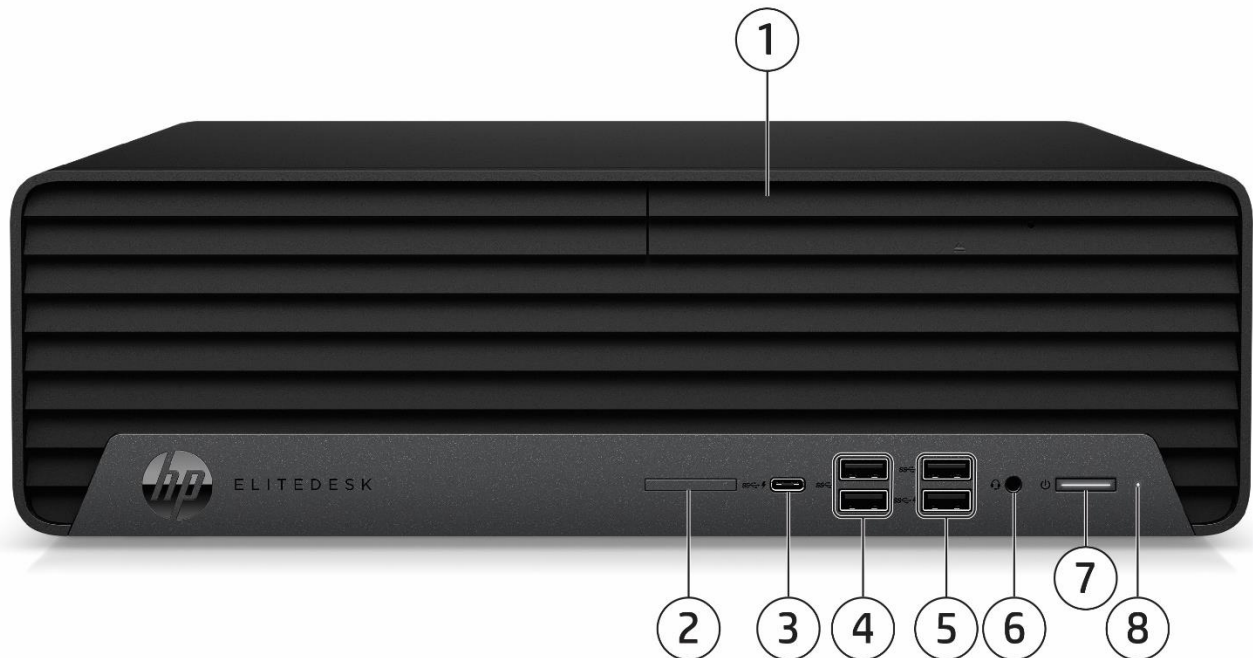
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| <ol style="list-style-type: none"> 1. (2) Dual-Mode DisplayPort™ 1.4 (DP++) 2. Type-A SuperSpeed USB 5Gbps signaling rate port 3. Type-A SuperSpeed USB 5Gbps signaling rate port (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS) 4. Type-A SuperSpeed USB 10Gbps signaling rate port (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS) Cover release thumbscrew 5. Cover release thumbscrew 6. Standard cable lock slot (10 mm) 7. (1) Flex Port 1, choice of: <ul style="list-style-type: none"> • HDMI 2.0a • VGA 2.0a • DisplayPort™ 1.4 • Fiber NIC (100Mbps and 1Gbps)¹ • SerialPort (AMO only) • Thunderbolt 3 (AMO only) • Type-C™ SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode and 100W Power Intake • Intel® I225-LM 2.5 Gigabit Network Connection LOM (non-vPro) • Dual Type A SuperSpeed USB 10Gbps signaling rate port | <ol style="list-style-type: none"> 8. (1) Flex Port 2, choice of: <ul style="list-style-type: none"> • VR Ready NVIDIA GTX 1660 Ti discrete GPU • Dual Type-A Hi-Speed USB 480Mbps signaling rate port • SerialS-232 9. Type-A SuperSpeed USB 10Gbps signaling rate port 10. RJ45 network connector 11. External WLAN antenna opening 12. Power connector 13. Retractable Padlock loop |
|--|--|

Not Shown

- | | |
|----------|---|
| Slots | (1) Internal M.2 2230 connector for WLAN
(2) Internal M.2 SSD storage 2242 and 2280 connector |
| Bays | (1) 2.5- inch SATA drive Bay (not available on 125W processor) |
| Mounting | Support for <ul style="list-style-type: none"> - VESA Sleeve Standalone - Quick Release Bracket - B300/B500 Mounting bracket - Integrated Work Center Stand |

1. Fiber NIC (100Mbps and 1Gbps) cards would not be available in some selected Europe countries and Korea.

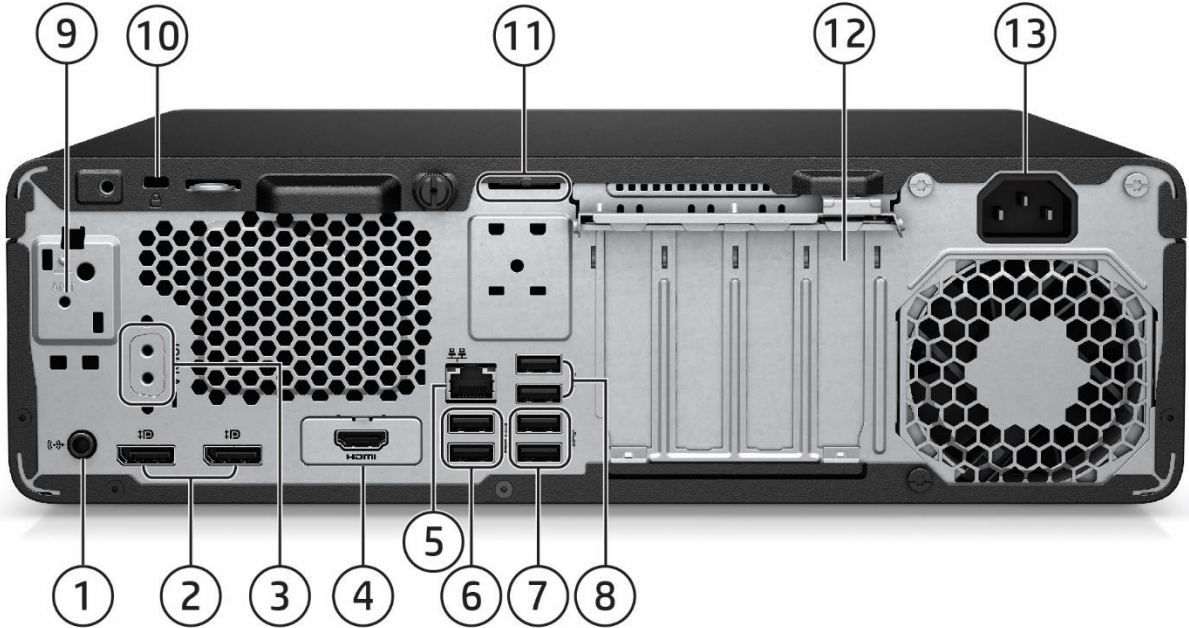
HP EliteDesk 800 G6 Small Form Factor Business PC



1. Optional Slim optical drive
2. Optional SD 4 Card Reader
3. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
4. Type A SuperSpeed USB 10Gbps signaling rate port (2)
5. Type A SuperSpeed USB 5Gbps signaling rate port (2) (1 with charge support up to 5V/1.5A)
6. Combo Audio Jack with CTIA and headset support
7. Dual-state power button
8. Hard drive activity light

Overview

HP EliteDesk 800 G6 Small Form Factor Business PC (Rear Image)



1. Audio line-out connector
2. Dual-Mode DisplayPort™ 1.4a (DP++) (2)
3. Optional Serial port (shown here not installed)
4. Optional port, choice of (shown here HDMI installed):
 - DisplayPort™
 - HDMI 2.0a
 - VGA
 - Dual Type A SuperSpeed USB 10Gbps signaling rate port
 - USB-C® SuperSpeed USB 10Gbps signaling rate port or serial port (USB-C® option has alt mode DisplayPort™ 1.4 and 15W output)
5. RJ45 network connector
6. Type A Hi-Speed USB 480 Mbps signaling rate port with wake from S4/S5 (2)
7. Type A SuperSpeed USB 10Gbps signaling rate port (2)
8. Type A SuperSpeed USB 5Gbps signaling rate port (2)
9. Optional Internal WLAN antenna cover (shown here not installed)
10. Standard cable lock slot
11. Optional intrusion sensor/hood lock (shown here not installed)
12. Optional Thunderbolt PCIe card with USB-C® (shown here not installed)
13. Power cord connector

Not shown

Slots

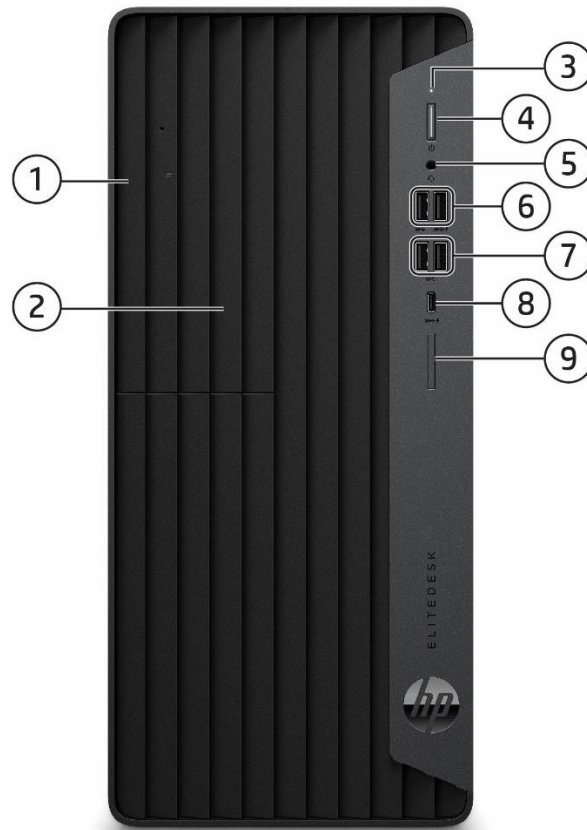
- (2) PCI Express x16 graphics connectors; one wired as an x4
- (2) PCI Express x1
- (2) internal M.2 SSD storage (2230 and 2280 connector)
- (1) internal M.2 WLAN (2230 connector)

Bays

- (1) 2.5" internal storage drive bay
- (2) 3.5" internal storage drive bay (convertible to 2.5")
- (1) 9.5 mm slim optical drive bay

Overview

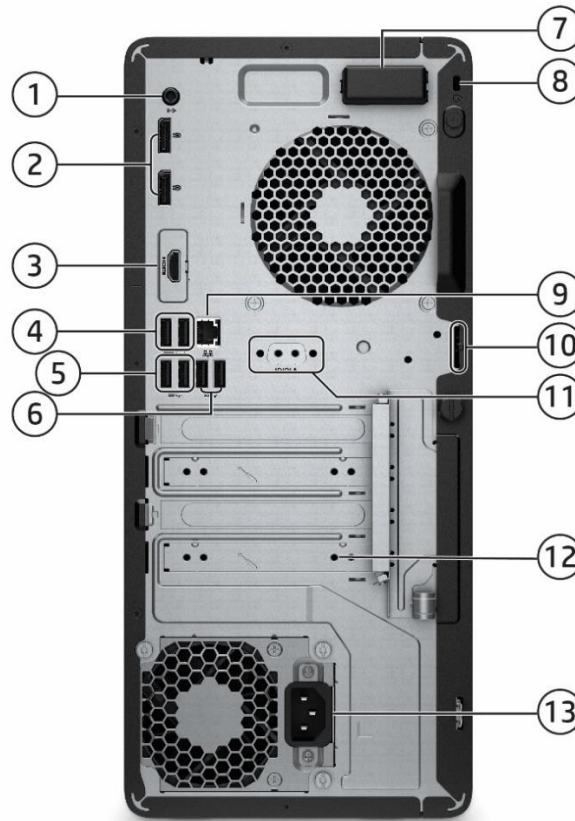
HP EliteDesk 800 G6 Tower Business PC



1. Optional Slim optical drive
2. External 5.25-inch Half-Height Drive Bay (behind bezel)
3. Hard drive activity light
4. Dual-state power button
5. Combo Audio Jack with CTIA and headset support
6. Type A SuperSpeed USB 5Gbps signaling rate port (charge support up to 5V/1.5A) (2)
7. Type-A SuperSpeed USB 10Gbps signaling rate port (2)
8. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
9. Optional SD card 4.0 reader

Overview

HP EliteDesk 800 G6 Tower Business PC



5.5

- | | |
|---|--|
| <ol style="list-style-type: none"> 1. Audio line-out jack for powered audio devices 2. Dual-Mode DisplayPort™ 1.4 (DP++) (2) 3. Optional port, choice of (shown here HDMI installed): <ul style="list-style-type: none"> • DisplayPort™ 1.4 • HDMI 2.0a • VGA • USB-C® SuperSpeed USB 10Gbps signaling rate port or serial port (USB-C® option has alt mode DisplayPort™ 1.4 and 15W output) 4. Type A Hi-Speed USB 480 Mbps signaling rate port with wake from S4/S5 (2) 5. Type A SuperSpeed USB 10Gbps signaling rate port (2) | <ol style="list-style-type: none"> 6. Type A SuperSpeed USB 5Gbps signaling rate port (2) 7. Optional Internal WLAN antenna cover (shown here installed) 8. Standard cable lock slot 9. RJ-45 (network) jack 10. Optional intrusion sensor/hood lock (shown here not installed) 11. Optional serial port (shown here not installed) 12. Optional Thunderbolt PCIe card with USB-C® (shown here not installed) 13. Power cord connector |
|---|--|

Not shown

Slots

- (2) PCI Express x16 graphics connectors; one wired as an x4
- (2) PCI Express x1
- (2) internal M.2 SSD storage (2242 and 2280 connector)
- (1) internal M.2 WLAN (2230 connector)

Bays

- (1) 2.5" internal storage drive bay
- (2) 3.5" internal storage drive bay (convertible to 2.5")
- (1) 5.25" half-height drive bay
- (1) 9.5mm slim optical drive bay

Overview

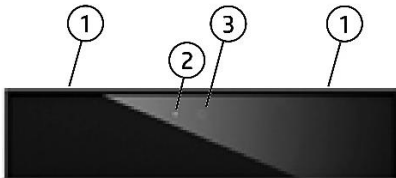
HP EliteOne 800 G6 24 & 27 All-in-One*



1. Camera (optional)

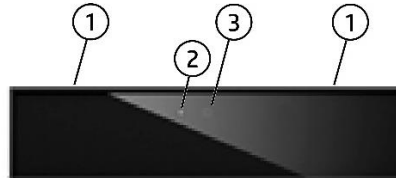
2. Speakers (optional)

Front / Rear facing 5MP Webcam (optional)



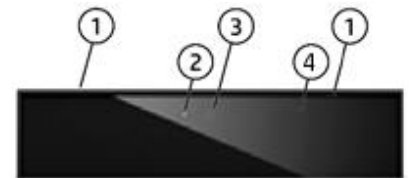
- 1. Dual Microphones
- 2. Webcam Light
- 3. Front / Rear facing 5MP Webcam

5MP Webcam (optional)



- 1. Dual Microphones
- 2. Webcam Light
- 3. 5MP Webcam

5MP Webcam with Infrared (IR) Sensors (optional)



- 1. Dual Microphones
- 2. Webcam Light
- 3. IR/5MP Webcam
- 4. IR Light

*Available Options: Touch, Non-Touch, HP Sure View (24" Display Only), and Discrete Graphics

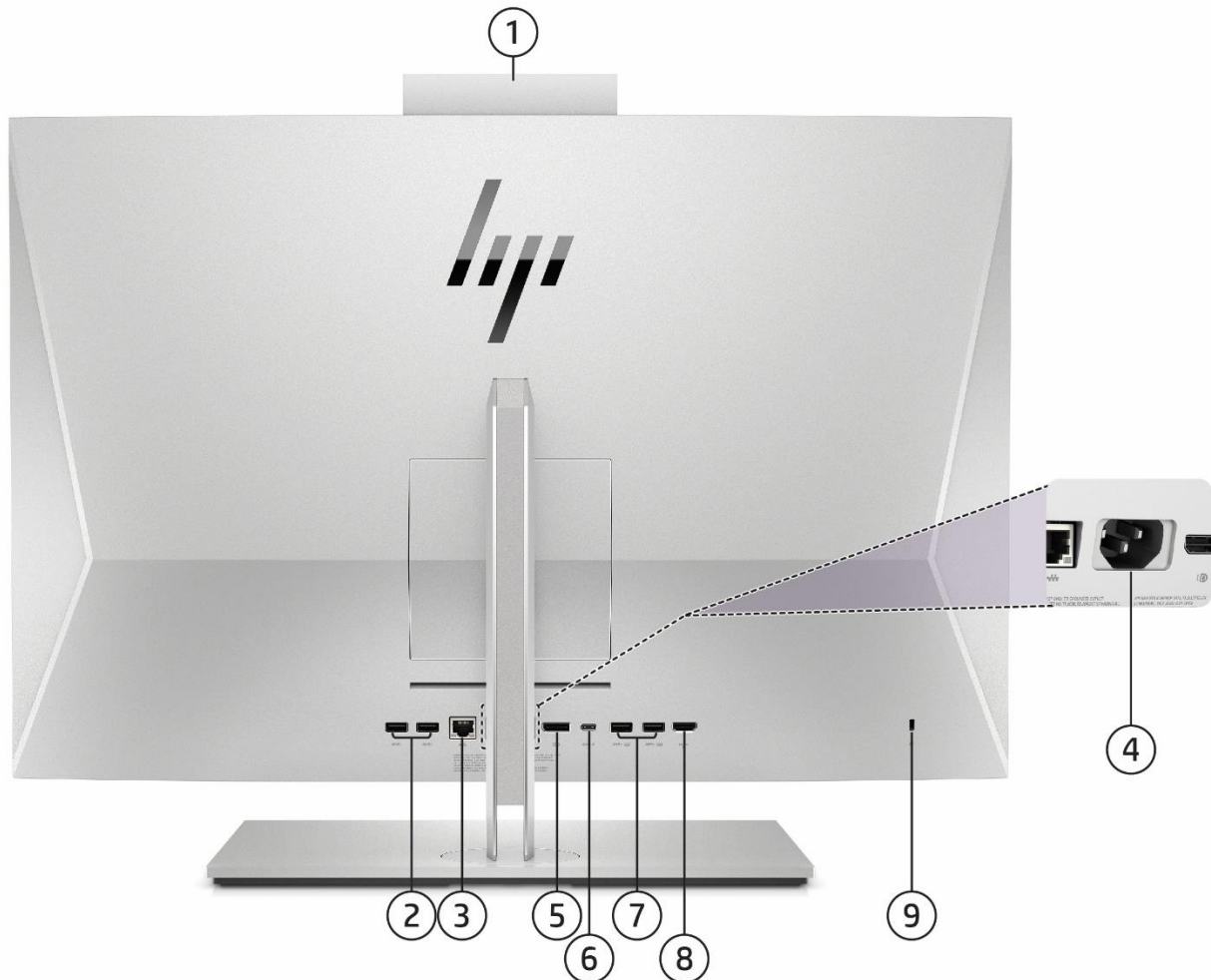
HP EliteOne 800 G6 24 & 27 All-in-One*



1. Type-A SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
2. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
3. Combo Audio Jack with CTIA and OMTP headset Support

Overview

HP EliteOne 800 G6 24 & 27 All-in-One

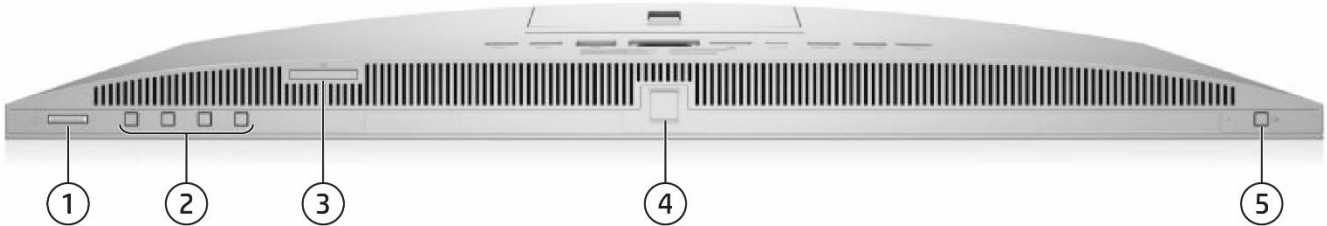


Rear components and rear ports

1. Camera (optional)
2. Type-A SuperSpeed USB 10Gbps signaling rate port (x2)
3. RJ-45 network connector/jack
4. Power Connector
5. Dual-Mode DisplayPort™1.4 (DP++)
6. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to (5V/3A)
7. Type-A SuperSpeed USB 5Gbps signaling rate port (x2)
8. HDMI-in 2.0a connector
9. Standard cable lock slot

Overview

HP EliteOne 800 G6 24 & 27 All-in-One



Bottom

1. Dual-State Power button
2. OSD control buttons
3. SD card reader 4.0 (optional)
4. Fingerprint Sensor (optional)
5. HP Sure View Button (optional on 23.8" only)

Not shown

Slots

- (1) internal M.2 PCIe x1 connector for optional wireless NIC
- (2) internal M.2 PCIe x4 connector for optional m.2 SSD

VESA

Support for VESA 100 mounting system on back of PC chassis (mounting hardware sold separately)

Features

AT A GLANCE

- Choice of four form factors: Tower, Small Form Factor, Desktop Mini and All-In-One
- HP developed and engineered UEFI V2.7 BIOS supporting security, manageability and software image stability
- Intel® Q470 chipset supporting Intel® 10th generation Core™ processors, featuring integrated Intel® UHD Graphics and Intel® vPro™ Technology (available with Core i3, Core i5, Core i7 and Core i9 processors) ^{1,4}
- Processors up to 65W on AiO
- Processors up to 125W on DM, TWR and SFF
- Intel® Optane™ Memory H10 with Solid State Storage
- Intel® UHD graphics with optional discrete graphics configure systems to up to 7 monitors (TWR, SFF and DM 35W)
- Intel® Ethernet Connection I219LM GbE LOM integrated network connection
- Intel® Wi-Fi 6 + BT5 (802.11AX 2x2)
- DDR4 Synchronous Dynamic Random Access Memory (SDRAM) (Transfer rates up to 2933 MT/s)²
- Support for up to 7 monitors via two standard DisplayPort™ 1.4 ports, a configurable Flex i/o port for video options and a discrete graphics card on TWRs, SFFs and DMs. AiO supports up to two additional monitors via DisplayPort™ or Type-C® USB in alternate mode.
- Configurable FlexPort which provides the following choices: HDMI 2.0, Serial, VGA, DisplayPort™ 1.4, or USB Type-C™ with DisplayPort™ 1.4 (USB Type-C® with DisplayPort™ 1.4 with Power Delivery [PD] on DMs), Thunderbolt 3.0 (port on DM, PCIe card on TWR, SFF) and Dual USB Type-A for (TWRs, SFFs and DMs). See Ports section for port availability by platform. FlexPort not supported on AiO.
- 2nd FlexPort available for configuration on the HP EliteDesk G6 Desktop Minis with the following ports: Serial, and Dual USB Type-A. FlexPort not supported on AiO.
- Configurable NVIDIA® GeForce® VR ready discrete graphics card with (3) mini-DisplayPorts and (1) micro-HDMI video port for DM⁵ to support up to (7) monitors with minimum 4K resolution and option to connect up to (3) monitors with 5K resolution via graphics card.
- Configurable AMD® Radeon and NVIDIA® GeForce® VR ready discrete graphics on AiO.⁵
- Configurable AMD® Radeon, NVIDIA® GeForce® and NVIDIA® Quadro® VR ready discrete graphics on TWR ⁵
- Compatibility with HP Mini-In-One 24 Display (800 G6 DM with 100W USB-C +PD option card)
- Compatible with HP Reverb VR Headset⁸ (AiO and TWR)
- Models can be configured with multiple data drives in a RAID array and support RAID 1 configured from factory. To enable RAID 1 function, it should be configured with the same type and capacity storage device. Besides, RAID function could be enabled by user themselves. SFF and Tower are able to support a 3rd non-RAID drive when two drives are configured with RAID but DM would not.
- Zoom Rooms edition available (AiO, DM) with Win IoT
- Audio by Bang & Olufsen (AiO)
- Intel® Unite™ available (AiO, DM)⁶
- Integrated Low Blue Light Panels on AiO (excludes Sure View and Touch Models)
- Enhanced Security with HP Security Suite (Refer to Security Section for details)
- ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See <http://www.epeat.net> for registration status by country. According to IEEE 1680.1-2018.⁷
- CCC, CECP and SEPA Certified (TWR/SFF/DM/AiO)
- TCO Edge for AiO (TCO Edge not available for models with HP Sure View)
- TCO (TWR/SFF/DM)
- PC chassis and all internal components and modules are manufactured with low halogen content ³
- Dust filter available for following platforms (35W DM, SFFs and TWRs)
- All form factors undergo up to 13 MIL-STD tests⁹
- Protected by HP Services, including limited warranties up to 3-3-3 (terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support
- Compliance with CE (Class B) / FCC (Class B) / UL (UL60950-1 / UL62368-1) / CSA (CSA C22.2 No.60950-1-07 / CSA C22.2 No. 62368-1-14) / ICES-003 / CCC / VCCI (Class B) / KCC (Class B)
- Fiber NIC (100Mbps and 1Gbps) cards would not be available in some selected European countries and Korea.

Features

1. Multi core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
2. Maximum transfer rate only available with Intel® Core i7 and Core i9 Processors.
3. External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.
4. Some functionality of vPro technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependant on 3rd party software providers. Compatibility of this generation of Intel vPro technology-based hardware with future "virtual appliances" is yet to be determined.
5. VR-ready as optional feature, requires specific configuration to support.
6. Intel® Unite™ must be configured at the factory.
7. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit <http://www.epeat.net> for more information.
8. Availability may vary by country.
9. MIL-STD drop test not performed for All-in-Ones. MIL-STD testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective feature 's sections

PRODUCT NAME

HP EliteDesk 800 G6 Tower PC
HP EliteDesk 800 G6 Small Form Factor PC
HP EliteDesk 800 G6 Desktop Mini PC
HP EliteOne 800 G6 24 All-in-One PC
HP EliteOne 800 G6 27 All-in-One PC

OPERATING SYSTEM

Preinstalled	Windows 11 Pro (Windows 11 Enterprise or Windows 10 Enterprise available with a Volume Licensing Agreement) ¹ Windows 11 Pro Education ¹ Windows 11 Home - HP recommends Windows 11 Pro for business ¹ Windows 11 Home Single Language - HP recommends Windows 11 Pro for business ¹
Web-supported only	Windows 11 Pro (preinstalled with Windows 10 Pro Downgrade) ^{1,2}

1. Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).
 2. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees apply and additional requirements may apply over time for updates.
- See <http://www.windows.com>.

NOTE: HP tested Windows 10, version 1909 on this platform. For testing information on newer versions of Windows 10, please see <https://support.hp.com/document/c05195282>.

Features

SUPPORTED VERSIONS

HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of Windows 10, please see <https://support.hp.com/document/c05195282>

CHIPSET

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Q470 PCH-H- vPro™	X	X	X	X

PROCESSORS

Intel® 10th Generation Core™ Processors	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Core™ i9 10900K Processor with Intel® UHD Graphics 630 (3.7GHz, up to 5.3 GHz with Intel® Turbo Boost ³ , 20MB cache, 10 cores) 125W ^{1,2,4} Supports Intel® vPro™ Technology ⁴	X	X	X	
Intel® Core™ i9 10900 Processor with Intel® UHD Graphics 630 (2.8GHz, up to 5.2 GHz with Intel® Turbo Boost ³ , 20MB cache, 10 cores) 65W ^{1,2} Supports Intel® vPro™ Technology ⁴	X	X	X	X
Intel® Core™ i9 10900T Processor with Intel® UHD Graphics 630 (1.9GHz, up to 4.6 GHz with Intel® Turbo Boost ³ , 20MB cache, 10cores) 35W ^{1,2} Supports Intel® vPro™ Technology ⁴	X			
Intel® Core™ i7 10700K Processor with Intel® UHD Graphics 630 (3.8 GHz, up to 5.1 GHz with Intel® Turbo Boost ³ , 16MB cache, 8 cores) 125W ^{1,2,4} Supports Intel® vPro™ Technology ⁴	X	X	X	
Intel® Core™ i7 10700 processor with Intel® UHD Graphics 630 (2.9 GHz, up to 4.8 GHz with Intel® Turbo Boost ³ , 16 MB cache, 8 cores) 65W ^{1,2} Supports Intel® vPro™ Technology ⁴	X	X	X	X
Intel® Core™ i7 10700T Processor with Intel® UHD Graphics 630 (2.0 GHz, up to 4.5 GHz with Intel® Turbo Boost ³ , 16MB cache, 8 cores) 35W ^{1,2} Supports Intel® vPro™ Technology ⁴	X			
Intel® Core™ i5 10600K processor with Intel® UHD Graphics 630 (4.1 up to 4.8 GHz with Intel® Turbo Boost ³ , 12 MB cache, 6 cores) 125W ^{1,2,4} Supports Intel® vPro™ Technology ⁴	X	X	X	
Intel® Core™ i5 10600 processor with Intel® UHD Graphics 630 (3.3 GHz, 12 MB cache, 6 cores) 65W ^{1,2} Supports Intel® vPro™ Technology ⁴	X	X	X	X
Intel® Core™ i5 10600T processor with Intel® UHD Graphics 630 (2.4 GHz 12 MB cache, 6 cores) 35W ^{1,2} Supports Intel® vPro™ Technology ⁴	X			
Intel® Core™ i5 10500 processor with Intel® UHD Graphics 630 (3.1 GHz, 12 MB cache, 6 cores) 65W ^{1,2} Supports Intel® vPro™ Technology ⁴	X	X	X	X
Intel® Core™ i5 10500T processor with Intel® UHD Graphics 630 (2.3 GHz, 12 MB cache, 6 cores) 35W ^{1,2} Supports Intel® vPro™ Technology ⁴	X			

Features

	DM	SFF	TWR	AiO
Intel® Core™ i5 10400 processor with Intel® UHD Graphics 630 (2.9 GHz, 12 MB cache, 6 cores) 65W ^{1, 2}	X	X	X	X
Intel® Core™ i5 10400T processor with Intel® UHD Graphics 630 (2.0 GHz, 12 MB cache, 6 cores) 35W ^{1, 2}	X			
Intel® Core™ i3 10325 processor with Intel® UHD Graphics 630 (3.9 GHz, 8MB cache, 4 cores) 65W ^{1, 2}	X	X	X	X
Intel® Core™ i3 10320 processor with Intel® UHD Graphics 630 (3.8 GHz, 8 MB cache, 4 cores) 65W ¹	X	X	X	X
Intel® Core™ i3 10305 processor with Intel® UHD Graphics 630 (3.8 GHz, 8MB cache, 4 cores) 65W ¹	X	X	X	X
Intel® Core™ i3 10305T processor with Intel® UHD Graphics 630 (3.0 GHz, 8MB cache, 4 cores) 35W ¹	X			
Intel® Core™ i3 10300 processor with Intel® UHD Graphics 630 (3.7 GHz, 8 MB cache, 4 cores) 65W ¹	X	X	X	X
Intel® Core™ i3 10300T processor with Intel® UHD Graphics 630 (3.0 GHz, 8 MB cache, 4 cores) 35W ¹	X			
Intel® Core™ i3 10105 processor with Intel® UHD Graphics 630 (3.7 GHz, 6MB cache, 4 cores) 65W ¹	X	X	X	X
Intel® Core™ i3 10105T processor with Intel® UHD Graphics 630 (3.0 GHz, 6MB cache, 4 cores) 35W ¹	X			
Intel® Core™ i3 10100 processor with Intel® UHD Graphics 630 (3.6 GHz, 6 MB cache, 4 cores) 65W ¹	X	X	X	X
Intel® Core™ i3 10100T processor with Intel® UHD Graphics 630 (3.0 GHz, 6 MB cache, 4 cores) 35W ¹	X			

1: Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a mea configuration surement of higher performance.

2. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system.

3. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system. See <http://www.intel.com/technology/turboboost> for more information.

4. Some functionality of vPro technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependent on 3rd party software providers. Compatibility with future "virtual appliances" is yet to be determined.

NOTE: Memory speed 2666 and 2933 MT/s can be achieved via two UDIMMs per channel (2DPC) when populated with the same part number.

Features

Intel® Pentium® Processors	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Pentium® Gold G6605 processor with Intel® UHD Graphics 630 (4.3GHz, 4 MB cache, 2 cores) 65W ¹	X	X	X	X
Intel® Pentium® Gold G6600 processor with Intel® UHD Graphics 630 (4.2 GHz, 4 MB cache, 2 cores) 65W ¹	X	X	X	X
Intel® Pentium® Gold G6505 processor with Intel® UHD Graphics 630 (4.2GHz, 4 MB cache, 2 cores) 65W ¹	X	X	X	X
Intel® Pentium® Gold G6505T processor with Intel® UHD Graphics 630 (3.6GHz, 4 MB cache, 2 cores) 35W ¹	X			
Intel® Pentium® Gold G6500 processor with Intel® UHD Graphics 630 (4.1 GHz, 4 MB cache, 2 cores) 65W ¹	X	X	X	X
Intel® Pentium® Gold G6500T processor with Intel® UHD Graphics 630 (3.5GHz, 4 MB cache, 2 cores) 35W ¹	X			
Intel® Pentium® Gold G6405 processor with Intel® UHD Graphics 610 (4.1GHz, 4 MB cache, 2 cores) 65W ¹	X	X	X	X
Intel® Pentium® Gold G6405T processor with Intel® UHD Graphics 610 (3.5GHz, 4 MB cache, 2 cores) 35W ¹	X			
Intel® Pentium® Gold G6400 processor with Intel® UHD Graphics 610 (4.0 GHz, 4 MB cache, 2 cores) 65W ¹	X	X	X	X
Intel® Pentium® Gold G6400T processor with Intel® UHD Graphics 610 (3.4 GHz, 4 MB cache, 2 cores) 35W ¹	X			

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Features

GRAPHICS

Integrated Intel® Graphics

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® UHD Graphics 630 (integrated on 10 th gen Core i9/i7/i5/i3, Pentium® Gold G6600, G6500)	X	X	X	X
Intel® UHD Graphics 610 (integrated on 10 th gen Pentium® Gold G6400, Celeron® G5900, G5920)	X	X	X	X

Optional Discrete Graphics Solutions

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
NVIDIA® GeForce® RTX 2080 Super 8GB FH 3DP HDMI Graphics Card*			X	
NVIDIA® GeForce® RTX 2070 Super 8GB FH 3DP HDMI Graphics Card				X
NVIDIA® GeForce® RTX 2060 Super 8GB FH DP HDMI DVI-D Graphics Card*			X	
NVIDIA® Quadro P2200 5GB 4DP Graphics Card			X	
NVIDIA® Quadro P1000 4GB 4mDP Graphics Card			X	
NVIDIA® Quadro P620 2GB Graphics Card		X	X	
NVIDIA® Quadro P400 2GB Graphics Card		X	X	
NVIDIA® GeForce® GTX 1660Ti 6GB HMDI, DP Graphics Card**	X			
AMD® Radeon™ RX 5300M 3GB NGC Graphics Card				X
AMD® Radeon™ RX 550X 4GB DP HDMI Graphics Card		X	X	
AMD® Radeon™ R7 430 2GB GDDR5 64bit DP+VGA***		X	X	
AMD® Radeon™ R7 430 2GB GDDR5 64bit 2DP		X	X	

*Requires 550W chassis

** Only available on the Desktop Mini with a 35W Processor and supports (3) Mini DP 1.4 Ports and (1) Micro –HDMI 2.0 port in order to drive up to 7 displays directly on the Desktop Mini.

***Not available in all regions

NOTE: The TWR can support a single discrete graphics card up to 300W with a 550W Power Supply.

Adapters and Cables

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP DisplayPort™ Cable	X	X	X	X
HP DisplayPort™ to DVI-D Adapter	X	X	X	X
HP DisplayPort™ to HDMI True 4K Adapter	X	X	X	X
HP DisplayPort™ to VGA Adapter	X	X	X	X
HP USB to Serial Port Adapter	X	X	X	X
HP USB-C® to HDMI 4K Adapter	X	X	X	X
HP USB-C® to DisplayPort Adapter	X	X	X	X
HP DVI Cable	X			X
HP HDMI Standard Cable Kit (HDMI)		X	X	X
HP DVI Cable Kit	X			X
Micro HDMI to HDMI Adapter	X	X	X	
Mini DisplayPort to DisplayPort Adapter	X			

Features

STORAGE

3.5 inch SATA Hard Disk Drives (HDD)

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
500GB 7200RPM 3.5in SATA HDD		X	X	
1TB 7200RPM 3.5in SATA HDD		X	X	
2TB 7200RPM 3.5in SATA HDD		X	X	

2.5 inch SATA Hard Disk Drives (HDD)

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
500GB 7200RPM 2.5in SATA HDD	X	X	X	
1TB 7200RPM 2.5in SATA HDD	X	X	X	
2TB 5400RPM 2.5in SATA HDD	X	X	X	
500GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD*	X	X	X	
500GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD*	X	X	X	

M.2 PCIe NVMe Solid State Drives (SSD)

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
256GB M.2 2280 PCIe NVMe SSD	X	X	X	X
512GB M.2 2280 PCIe NVMe SSD	X	X	X	X
128GB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
256GB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
512GB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
1TB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
2TB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD*	X	X	X	X
512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD*	X	X	X	X
256GB Intel® Optane™ Memory H10 with Solid State Storage*	X	X	X	X
512GB Intel® Optane™ Memory H10 with Solid State Storage*	X	X	X	X

Optical Disc Drives

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP 9.5mm Slim DVD-ROM Drive		X	X	
HP 9.5mm Slim DVD Writer Drive		X	X	
HP 9.5mm Slim Blu-Ray Writer Drive		X	X	

Media Card Reader

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
SD 4.0 with 5-in-1 Interface (Supports SD, SDXC, SDHC, UHS-I, UHS-II)		X	X	X

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Features

MEMORY

Memory Type

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
DDR4-2666 (Transfer rates up to 2666 MT/s*), 2 SODIMM	X			X
DDR4-3200 (Transfer rates up to 2933 MT/s**), 4 DIMM	X			X
DDR4-2666 (Transfer rates up to 2666 MT/s*), 2 SODIMM		X	X	
DDR4-3200 (Transfer rates up to 2933 MT/s**), 4 DIMM		X	X	

NOTE*: for i5 and below processor.

NOTE**: for i7 and i9 processor.

NOTE:

1. Actual system speed is determined by the processor configured. See processor specifications for supported memory data rate.
2. Memory speed 2666 and 2933 MT/s can be achieved via two UDIMMs per channel (2DPC) when populated with the same part number.
3. All memory slot are customer accessible/upgradeable.
4. For system configured with more than 3GB of memory and a 32-bit operation system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.

Memory Configuration

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
4 GB (1 x 4 GB)	X	X	X	X
8 GB (2 x 4 GB)	X	X	X	X
8 GB (1 x 8 GB)	X	X	X	X
16 GB (2 x 8 GB)	X	X	X	X
16 GB (1 x 16 GB)	X	X	X	X
32 GB (2 x 16 GB)	X	X	X	X
32 GB (4 x 8 GB)		X	X	
32 GB (1 x 32 GB)	X	X	X	X
64 GB (4 x 16 GB)		X	X	
64 GB (2 x 32 GB)	X	X	X	X
128 GB (4 x 32 GB)		X	X	

Features

NETWORKING/COMMUNICATIONS

Ethernet (RJ-45)

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® I219-LM 1 Gigabit Network Connection LOM (vPro)	X	X	X	X
Intel® I225LM 2.5 Gigabit Network Connection LOM (optional)	X			
Intel® Ethernet I210-T1 PCIe x1 Gb Network Interface Card (optional)		X	X	

Wireless¹

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Wi-Fi 6 AX201 + BT5.2 Wireless Card (802.11AX 2x2 vPro, supporting gigabit file transfer speed)	X	X	X	X
Intel® Wi-Fi 6 AX201 + BT5.2 Wireless Card (802.11AX 2x2 non-vPro, supporting gigabit file transfer speed)	X	X	X	X
Realtek RTL8822CE 802.11ac 2x2 Wi-Fi® + BT5.0 Wireless Card	X	X	X	X

1. Wireless access point and Internet service required and not included. Availability of public wireless access points limited. The specifications for the 802.11ax WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the PC to communicate with 802.11ax WLAN devices. Wi-Fi 6 requires a wireless router, sold separately, that supports 802.11ax (Wi-Fi 6). Only available in countries where 802.11ax is supported.

Features

KEYBOARDS AND POINTING DEVICES

Keyboards

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP Wired Desktop 320K Keyboard	X	X	X	X
HP USB Premium Keyboard	X	X	X	X
HP USB and PS/2 Washable Keyboard ¹	X	X	X	X
HP USB Business Slim Smart Card (CCID) Keyboard	X	X	X	X
HP USB Keyboard	X	X	X	X
HP PS/2 Business Slim Keyboard ¹		X	X	
HP Wireless Business Slim Keyboard and Mouse	X	X	X	X
HP USB Business Slim Antimicrobial Keyboard ²	X	X	X	X
HP Wireless Premium Keyboard and Mouse	X	X	X	X
HP USB Keyboard and Mouse Healthcare Edition	X	X	X	X

Mouse

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP Wired Desktop 320M Mouse	X	X	X	X
HP PS/2 Mouse ¹		X	X	
HP USB Optical Mouse	X	X	X	X
HP USB Premium Mouse	X	X	X	X
HP USB 1000dpi Laser Mouse	X	X	X	X
HP USB and PS/2 Washable Mouse ¹	X	X	X	
Antimicrobial USB Mouse ²	X	X	X	X
HP USB Hardened Mouse ²	X	X	X	X
HP USB Fingerprint Reader Mouse	X	X	X	X

1. PS/2 port not available on EliteOne 800 G6 AiOs and not available on any EliteDesk 800 G6 DMs

2. Not available in all regions

Features

SECURITY

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
TPM 2.0 (FW: 7.85) endpoint security controller (Infineon SLB9670) shipped with Windows 10. Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified.	X	X	X	X
Solenoid Lock & Intrusion Sensor		X	X	
Intrusion Sensor for DM/AiO (integrated in the PCA, can be enabled/disabled through BIOS)	X			X
Support for chassis cable lock devices	X (10 mm or smaller)	X	X	X
Support for chassis padlocks devices	X	X	X	
HP Fingerprint Sensor (standard on 800 G6 AiO touch models and optional on non-touch models)				X
SATA port disablement (via BIOS)	X	X	X	
Serial, USB enable/disable (via BIOS)	X	X	X	X
Intel® Identify Protection Technology (IPT) ¹	X	X	X	X
Serial, parallel, USB enable/disable (via BIOS)	X	X	X	X
Optional USB Port Disable at factory (user configurable via BIOS)	X	X	X	X
Removable media write/boot control	X	X	X	X
Power-on password (via BIOS)	X	X	X	X
Setup password (via BIOS)	X	X	X	X

1. Models configured with Intel® Core™ processors have the ability to utilize advanced security protection for online transactions. IPT, used in conjunction with participating web sites, provides double identity authentication by adding a hardware component in addition to the usual user name and password. IPT is initialized through an HP Client Security module.

PORTS

I/O Ports – Internal Ports

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Internal SATA storage connector(s)	N/A	3	4	N/A
Internal SATA storage connector (Data and Power)	1	N/A	N/A	N/A

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

Standard User Accessible Ports

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Type-A Hi-Speed USB		2 (rear)	2 (rear)	
Type-A SuperSpeed USB 5 Gbps signaling rate port	1 (front) 2 (rear)	2 front (1 fast charging), 2 rear	2 front (1 fast charging), 2 rear	2 rear
Type-A SuperSpeed USB 10 Gbps signaling rate port	1 (front) 2 (rear)	2 front; 2 rear	2 front; 2 rear	2 rear 1 side
Type-C® SuperSpeed USB 10 signaling rate Gbps port	1 (front)	1 (front)	1 (front)	1 rear 1 side

Features

Video	2 DisplayPort™ 1.4 (rear)	2 DisplayPort™ 1.4 (rear)	1 DisplayPort™ 1.4 (rear)	For models with integrated graphics: 1 DisplayPort™ 1.4 (rear) 1 USB Type-C® with alt mode display or 15W output (rear) 1 HDMI-In (rear) For models with discrete graphics: 1 DisplayPort™ 1.4 (rear) 1 USB Type-C® with alt mode display or 15W output (rear) 1 HDMI-In (rear)
Audio	1 Combo Audio Jack with CTIA and headset support (front)	1 Universal Audio Jack with CTIA headset support (front); 1 Audio-out (rear),	1 Universal Audio Jack with CTIA headset support (front); 1 Audio-out (rear),	1 CTIA/OMTP UAJ (side)
Network Interface	1 RJ45 (rear)	1 RJ45 (rear)	1 RJ45 (rear)	1 RJ45 (rear)

(1) Flexible Port 1, choice of one of the following...

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Type-A SuperSpeed USB 5 Gbps signaling rate port	2 (rear)	2 (rear)	2 (rear)	N/A
Type-C® SuperSpeed USB 10Gbps signaling rate port	1 SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode and power intake via USB Type-C® Power Delivery up to 100W (rear)	1 SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode (rear)	1 SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode (rear)*	N/A
Thunderbolt™ 3	1 (rear)	1 (rear)	1 (rear)	N/A
Video	1 DisplayPort™ 1.4 <u>or</u> HDMI 2.0 <u>or</u> VGA (rear)	1 DisplayPort™ 1.4 <u>or</u> HDMI 2.0 <u>or</u> VGA (rear)	1 DisplayPort™ 1.4 <u>or</u> HDMI 2.0 <u>or</u> VGA (rear)	N/A
Serial (RS-232)	N/A	1 (rear)	1 (rear)	N/A
Fiber NIC Adapter	(1) 100Mbps NIC (rear) (1) 1 Gbps NIC (rear)			N/A
RJ-45 Ethernet NIC	(1) 2.5GbE(rear)			N/A

(1) Flexible Port 2, choice of one of the following:

	<u>DM</u>	<u>SFF</u>	<u>MT</u>	<u>AiO</u>
Type-A USB	2 Hi-Speed USB (rear)			N/A
Serial (RS-232)	1 (rear)			N/A
Discrete Graphics	1 (rear)			N/A

Features

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

Slots	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
M.2 PCIe	(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage)	(1) M.2 WLAN+BT Combo; (1) M.2 2242/2280 for PCIe SSD storage, (1) M.2 2280 for PCIe SSD storage
PCI Express v3.0 x1	N/A	2	2	N/A
PCI Express v3.0 x16 (wired as x4)	N/A	1	1	N/A
PCI Express v3.0 x16	N/A	1 (up to 75W)	1 (up to 300W)	N/A

Bays	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
5.25" Half Height (External)	N/A	N/A	1	N/A
9mm Slim Optical Disc Drive (ODD)	N/A	1	1	N/A
SD Card Reader	N/A	1	1	1
2.5" Internal Storage Drive	1	1	1	N/A
3.5" Internal Storage Drive	N/A	2	2	N/A

SATA 2.5" internal storage drive cannot be selected if 2nd M.2, discrete graphic card, or 125W processor is selected.

Features

USB SPECIFICATION AND MARKETING NAME MAPPING TABLE

Marketing Name	Technical Terminology
Hi-Speed USB 480Mbps signaling rate	USB 2.0
SuperSpeed USB 5Gbps signaling rate	USB 3.2 Gen 1
SuperSpeed USB 10Gbps signaling rate	USB 3.2 Gen 2
SuperSpeed USB 20Gbps signaling rate	USB 3.2 Gen 2x2

Features

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS**BIOS**

HP BIOSphere Gen6¹
HP DriveLock & Automatic DriveLock²
BIOS Update via Network
HP Secure Erase³
Absolute Persistence Module⁴
Pre-boot Authentication
HP Wake on WLAN

Software

HP Desktop Support Utility
HP JumpStart
HP Privacy Settings
HP Setup Integrated OOBE
HP Support Assistant⁵
HP Noise Cancellation Software
Buy Office (sold separately)
HP Smart Support⁶

Manageability Features

HP Driver Packs⁷
HP System Software Manager (SSM) (download)
HP BIOS Config Utility (BCU) (download)
HP Client Catalog (download)
HP Image Assistant Gen (download)
HP Manageability Integration Kit for Microsoft System Center Configuration Management Gen4⁸
Ivanti Management Suite (download)⁹
HP Cloud Recovery¹⁰
HP Client Management Script Library (download)

Client Security Software

HP Client Security Suite Gen6¹¹
HP Power On Authentication
Windows Defender¹²

Security Management

Trusted Platform Module TPM 2.0 Embedded Security Chip shipped with Windows 10. (Common Criteria EAL4+ Certified).
SATA 0,1 port disablement (via BIOS)
Serial, USB enable/disable (via BIOS)
Power-on password (via BIOS)
Setup password (via BIOS)
Support for chassis padlocks and cable lock devices
HP Sure Sense¹³
HP Sure Click¹⁴
HP Sure Start Gen6¹⁵
HP Sure Run Gen3¹⁶
HP Sure Recover Gen3¹⁷

1. HP BIOSphere Gen6 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.
2. Storage Drivelock does not work with Self Encrypting or Optane based storage.
3. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
4. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a

Features

limited warranty. Certain conditions apply. For full details visit: <http://www.absolute.com/company/legal/agreements/computrace-agreement>. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

5. HP Support Assistant requires Windows and Internet access.

6. HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: <http://www.hp.com/smart-support>. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.

7. HP Driver Packs not preinstalled, however available for download at <http://www.hp.com/go/clientmanagement>.

8. HP Manageability Integration Kit can be downloaded from <http://www8.hp.com/us/en/ads/clientmanagement/overview.html>.

9. Ivanti Management Suite subscription required.

10. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: <https://support.hp.com/us-en/document/c05115630>.

11. HP Client Security Manager Gen6 requires Windows and is available on select HP Pro and Elite PCs.

12. Windows Defender Opt in Windows 10 and internet connection required for updates.

13. HP Sure Sense requires Windows 10.

14. HP Sure Click is available on most HP PCs and supports Microsoft® Internet Explorer, Google Chrome, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.

15. HP Sure Start Gen6 is available on select HP PCs with Intel processors.

16. HP Sure Run Gen3 is available on select Windows 10 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors.

17. HP Sure Recover Gen3 is available on select HP PCs and requires an open network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data.

Features

ENVIRONMENTAL & INDUSTRY

ENERGY STAR® certified models available

ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See <http://www.epeat.net> for registration status by country. According to IEEE 1680.1-2018.

Low halogen (chassis, all internal components and modules)¹
TAA compliant models available

1. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating: 50° to 95° F (10° to 35° C) ¹ Non-operating: -22° to 149° F (-30° to 65° C)
Relative Humidity	Operating: 10% to 90% (non-condensing at ambient) Non-operating: 5% to 95% (non-condensing at ambient)
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50000ft (15240 m)

1. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

Features

HP EliteDesk 800 Desktop Mini G6 series

Eco-Label Certifications & declarations	<p>This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:</p> <ul style="list-style-type: none"> • IT ECO declaration • US ENERGY STAR® • US Federal Energy Management Program (FEMP) • EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country. • TCO Certified • China Energy Conservation Program (CECP) • China State Environmental Protection Administration (SEPA) • Taiwan Green Mark • Korea Eco-label • Japan PC Green label • Commission Regulation (EC) No 617/2013 (ErP Lot 3) 		
System Configuration	<p>The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a “Typically Configured Desktop.”</p>		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	8.9320 W	8.9410 W	8.9190 W
Normal Operation (Long idle)	6.3380 W	6.3460 W	6.3280 W
Sleep	1.0520 W	1.1020 W	1.0320 W
Off	0.8210 W	0.8220 W	0.8200 W
	<p>NOTE: Energy efficiency data listed is for an ENERGY STAR® certified product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® certified configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.</p>		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	30.4581 BTU/hr	30.4888 BTU/hr	30.4138 BTU/hr
Normal Operation (Long idle)	21.6126 BTU/hr	21.6399 BTU/hr	21.5785 BTU/hr
Sleep	3.5873 BTU/hr	3.7578 BTU/hr	3.5191 BTU/hr
Off	2.7996 BTU/hr	2.8030 BTU/hr	2.7962 BTU/hr
	<p>NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.</p>		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)		Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle	2.8		18.8
Fixed Disk – Random writes	2.8		18.8
Longevity and Upgrading	<p>This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:</p> <p>Spare parts are available throughout the warranty period and or for up to “5” years after the end of production.</p>		

Features

Batteries	<p>This battery(s) in this product comply with EU Directive 2006/66/EC</p> <p>Batteries used in the product do not contain: Mercury greater the 1ppm by weight Cadmium greater than 20ppm by weight</p> <p>Battery size: CR2032 (coin cell) Battery type: Lithium</p>		
Additional Information	<ul style="list-style-type: none"> • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018. • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains a minimum of 35% post-consumer recycled plastic (by wt.); Including 10% ITE-derived post-consumer recycled plastic* • This product is 95.1% recycle-able when properly disposed of at end of life. <p>*NOTE: Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.</p>		
Packaging Materials	External:	PAPER/Corrugated	562 g
		PAPER/Molded pulp	74 g
	Internal:	PLASTIC/Polyethylene low density	16 g
Material Usage	<p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) 		

Features

<p>Packaging Usage</p>	<p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
<p>End-of-life Management and Recycling</p>	<p>HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p>

Features

HP EliteDesk 800 Small Form Factor G6 series

Eco-Label Certifications & declarations	<p>This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:</p> <ul style="list-style-type: none"> • IT ECO declaration • US ENERGY STAR® • US Federal Energy Management Program (FEMP) • EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country. • TCO Certified • China Energy Conservation Program (CECP) • China State Environmental Protection Administration (SEPA) • Taiwan Green Mark • Korea Eco-label • Japan PC Green label • Commission Regulation (EC) No 617/2013 (ErP Lot 3) 		
System Configuration	<p>The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a “Typically Configured Desktop.”</p>		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	12.479 watt	12.579 watt	12.291 watt
Normal Operation (Long idle)	11.193 watt	11.306 watt	11.151 watt
Sleep	0.675 watt	0.7	0.665 watt
Off	0.479 watt	0.5	0.475 watt
	<p>NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.</p>		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	42.55339 BTU/hr	42.89439 BTU/hr	41.91231 BTU/hr
Normal Operation (Long idle)	38.16813 BTU/hr	38.55346 BTU/hr	38.02491 BTU/hr
Sleep	2.30175 BTU/hr	2.40064 BTU/hr	2.26765 BTU/hr
Off	1.63339 BTU/hr	1.70841 BTU/hr	1.61975 BTU/hr
	<p>NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.</p>		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)		Sound Pressure (L_{pAm}, decibels)
Typically Configured – Idle	3.11		20.7
Fixed Disk–Random writes	3.41		22.1
Longevity and Upgrading	<p>This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:</p> <p>Spare parts are available throughout the warranty period and or for up to “5” years after the end of production.</p>		

Features

Batteries	<p>This battery(s) in this product comply with EU Directive 2006/66/EC</p> <p>Batteries used in the product do not contain: Mercury greater the 1ppm by weight Cadmium greater than 20ppm by weight</p> <p>Battery size: CR2032 (coin cell) Battery type: Lithium</p>		
Additional Information	<ul style="list-style-type: none"> • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See www.epeat.net for registration status by country. According to IEEE 1680.1-2018. • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains a minimum of 35% post-consumer recycled plastic (by wt.); Including 10% ITE-derived post-consumer recycled plastic* • This product is 95.1% recycle-able when properly disposed of at end of life. <p>*NOTE: Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.</p>		
Packaging Materials	External:	PAPER/Corrugated	1158 g
	Internal:	PAPER/Molded pulp	340 g
		PLASTIC/Polyethylene low density	28 g
Material Usage	<p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) 		

Features

Packaging Usage	<p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	<p>HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p>

HP EliteDesk 800 Tower G6 series

Eco-Label Certifications & declarations	<p>This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:</p> <ul style="list-style-type: none"> • IT ECO declaration • US ENERGY STAR® • US Federal Energy Management Program (FEMP) • EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country. • TCO Certified • China Energy Conservation Program (CECP) • China State Environmental Protection Administration (SEPA) • Taiwan Green Mark • Korea Eco-label • Japan PC Green label • Commission Regulation (EC) No 617/2013 (ErP Lot 3) 		
System Configuration	<p>The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a Typically Configured Desktop.</p>		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	11.67 W	11.24 W	11.53 W

Features

Normal Operation (Long idle)	9.83 W	10.55 W	9.69 W
Sleep	0.84 W	0.81 W	0.86 W
Off	0.57 W	0.53 W	0.57 W
	<p>NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.</p>		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	39.91 BTU/hr	38.44 BTU/hr	39.43 BTU/hr
Normal Operation (Long idle)	33.62 BTU/hr	36.08 BTU/hr	33.14 BTU/hr
Sleep	2.87 BTU/hr	2.77 BTU/hr	2.94 BTU/hr
Off	1.95 BTU/hr	1.81 BTU/hr	1.95 BTU/hr
	<p>NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.</p>		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)		Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle	3.3		21
Fixed Disk–Random writes	3.3		22
Longevity and Upgrading	<p>This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:</p> <p>Spare parts are available throughout the warranty period and or for up to “5” years after the end of production.</p>		
Batteries	<p>This battery(s) in this product comply with EU Directive 2006/66/EC</p> <p>Batteries used in the product do not contain: Mercury greater the 1ppm by weight Cadmium greater than 20ppm by weight</p> <p>Battery size: CR2032 (coin cell) Battery type: Lithium</p>		
Additional Information	<ul style="list-style-type: none"> • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See www.epeat.net for registration status by country. According to IEEE 1680.1-2018. • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains a minimum of 35% post-consumer recycled plastic (by wt.); Including 10% ITE-derived post-consumer recycled plastic* • This product is 95.1% recycle-able when properly disposed of at end of life. <p>*NOTE: Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.</p>		
Packaging Materials	External:	PAPER/Corrugated	1114 g
		PAPER/Molded Pulp	788 g

Features

	Internal: PLASTIC/Polyethylene low density - LDPE	44 g
Material Usage	<p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) 	
Packaging Usage	<p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. 	
End-of-life Management and Recycling	<p>HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and</p>	

Features

	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
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HP EliteOne 800 G6 23.8-in All-in-One

Eco-Label Certifications & declarations	<p>This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:</p> <ul style="list-style-type: none"> • IT ECO declaration • US ENERGY STAR® • US Federal Energy Management Program (FEMP) • EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country. • TCO Certified • China Energy Conservation Program (CECP) • China State Environmental Protection Administration (SEPA) • Taiwan Green Mark • Korea Eco-label • Japan PC Green label • Commission Regulation (EC) No 617/2013 (ErP Lot 3) 		
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the All-in-One PC model is based on a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	15.60 W	15.68 W	15.45 W
Normal Operation (Long idle)	5.57 W	5.65 W	5.41 W
Sleep	0.94 W	1.00 W	0.82 W
Off	0.84 W	0.87 W	0.81 W
	<p>NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.</p>		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	53.2028BTU/hr	53.4772 BTU/hr	52.691 BTU/hr
Normal Operation (Long idle)	19.02 BTU/hr	19.3 BTU/hr	18.5 BTU/hr
Sleep	3.2 BTU/hr	3.4 BTU/hr	2.8 BTU/hr
Off	2.9 BTU/hr	3 BTU/hr	2.8 BTU/hr
	<p>NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.</p>		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)	Sound Pressure (L _{pAm} , decibels)	



Features

Typically Configured – Idle	2.5	14
Fixed Disk – Random writes	2.5	15
Longevity and Upgrading	<p>This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:</p> <ul style="list-style-type: none"> • 6 USB ports • 2 memory slots • 1 Mini PCIe half-length slot • 1 MXM 3.0 Type A - 35W slot • 1 mSATA slot • 1 2.5" internal bay supporting up to Two 2.5" hard drives (HDD/SSD/SED/SSHD) • 1 5.25" external supporting optical drive <p>Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.</p>	
Batteries	<p>This battery(s) in this product comply with EU Directive 2006/66/EC</p> <p>Batteries used in the product do not contain: Mercury greater the 1ppm by weight Cadmium greater than 20ppm by weight</p> <p>Battery size: CR2032 (coin cell) Battery type: Lithium</p>	
Additional Information	<ul style="list-style-type: none"> • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680 (EPEAT) standard at the gold level, see www.epeat.net • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 51.7% post-consumer recycled plastic (by wt.) <i>according to IEEE 1680.1-2018 standard, criterion 4.2.1.1.</i> • This product is 97.8% recycle-able when properly disposed of at end of life. 	
Packaging Materials	External:	PAPER/Corrugated
	Internal:	PLASTIC/Polyethylene Expanded - EPE
		1.488 g
		1.052 g
	The plastic packaging material contains at least 90% recycled content.	
	The corrugated paper packaging materials contains at least 80% recycled content.	
RoHS Compliance	<p>HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.</p> <p>We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.</p> <p>We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.</p>	

Features

	To obtain a copy of the HP RoHS Compliance Statement, see Error! Hyperlink reference not valid. HP RoHS position statement.
Material Usage	<p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	<p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	<p>HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates:</p>

Features

	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
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HP EliteOne 800 G6 27 All-in-One PC

Eco-Label Certifications & declarations	<p>This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:</p> <ul style="list-style-type: none"> • IT ECO declaration • US ENERGY STAR® • US Federal Energy Management Program (FEMP) • EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country. • TCO Certified • China Energy Conservation Program (CECP) • China State Environmental Protection Administration (SEPA) • Taiwan Green Mark • Korea Eco-label • Japan PC Green label • Commission Regulation (EC) No 617/2013 (ErP Lot 3) 		
System Configuration	<p>The configuration used for the Energy Consumption and Declared Noise Emissions data for the All-in-One PC model is based on a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.</p>		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	22.57 W	22.65 W	22.42 W
Normal Operation (Long idle)	6.35 W	6.44 W	6.19 W
Sleep	1.47 W	1.52 W	1.35 W
Off	0.88 W	0.89 W	0.84 W
	<p>Note: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.</p>		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	76.967 BTU/hr	77.2467 BTU/hr	76.4556 BTU/hr
Normal Operation (Long idle)	21.7 BTU/hr	22 BTU/hr	21.2 BTU/hr
Sleep	5 BTU/hr	5.2 BTU/hr	4.6 BTU/hr
Off	3 BTU/hr	3 BTU/hr	2.9 BTU/hr
	<p>NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.</p>		

Features

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)	Sound Pressure (L _{pAm} , decibels)	
Typically Configured – Idle	2.5	15	
Fixed Disk – Random writes	2.6	16	
Longevity and Upgrading	<p>This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:</p> <ul style="list-style-type: none"> • 6 USB ports • 2 memory slots • 1 Mini PCIe half-length slot • 1 MXM 3.0 Type A - 35W slot • 1 mSATA slot • 1 2.5" internal bay supporting up to Two 2.5" hard drives (HDD/SSD/SED/SSHD) • 1 5.25" external supporting optical drive <p>Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.</p>		
Batteries	<p>This battery(s) in this product comply with EU Directive 2006/66/EC</p> <p>Batteries used in the product do not contain: Mercury greater the 1ppm by weight Cadmium greater than 20ppm by weight</p> <p>Battery size: CR2032 (coin cell) Battery type: Lithium</p>		
Additional Information	<ul style="list-style-type: none"> • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680 (EPEAT) standard at the gold level, see www.epeat.net • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 72.2% post-consumer recycled plastic (by wt.) <i>according to IEEE 1680.1-2018 standard, criterion 4.2.1.1.</i> • This product is 98% recycle-able when properly disposed of at end of life. 		
Packaging Materials	External:	PAPER/Corrugated	1.510 g
	Internal:	PLASTIC/Polyethylene Expanded - EPE	1.520 g
	The plastic packaging material contains at least xx% recycled content.		
	The corrugated paper packaging materials contains at least xx% recycled content.		
RoHS Compliance	<p>HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.</p> <p>We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.</p>		

Features

	<p>We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.</p> <p>To obtain a copy of the HP RoHS Compliance Statement, see:Error! Hyperlink reference not valid. HP RoHS position statement.</p>
<p>Material Usage</p>	<p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Bis(2-Ethylhexyl) phthalate (DEHP) • Benzyl butyl phthalate (BBP) • Dibutyl phthalate (DBP) • Diisobutyl phthalate (DIBP) • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
<p>Packaging Usage</p>	<p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

Features

<p>End-of-life Management and Recycling</p>	<p>HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p>
<p>HP, Inc. Corporate Environmental Information</p>	<p>For more information about HP's commitment to the environment:</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html</p> <p>Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html</p> <p>ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p>

Features

SERVICE AND SUPPORT**HP EliteDesk 800 G6 Tower Business PC**

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: <http://www.hp.com/go/cpc>.¹⁸

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.

18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

HP EliteDesk 800 G6 Small Form Factor Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: <http://www.hp.com/go/cpc>.¹⁸

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.

18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

HP EliteDesk 800 G6 Desktop Mini Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: <http://www.hp.com/go/cpc>.¹⁸

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.

18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Features

HP EliteOne 800 G6 24 & 27 All-in-One Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: <http://www.hp.com/go/cpc>.¹⁸

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.

18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

CERTIFICATION AND COMPLIANCE

Energy Efficiency Compliance

ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See <http://www.epeat.net> for registration status by country. According to IEEE 1680.1-2018.

PROCESSORS

Intel® 10th Generation Core™ Processors

All HP EliteDesk 800 G6 Business PC models featuring this technology include processors that are part of the Intel® Stable Image Platform Program (SIPP) designed to ensure the stability promise inherent in the value proposition of the HP EliteDesk and EliteOne 800 G6 Business PC.

Intel® Advanced Management Technology (AMT) v12 – An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 12 includes the following advanced management functions:

- Support for configuration of Intel AMT 12.0 new capabilities
- No reset after provisioning
- Support changes to BIOS table 130
- Support for Microsoft Windows Server 2012 R2
- Support for New Microsoft SQL Server Versions including Standard and Enterprise editions
- Support for Intel SSD Prop 2500 Series
- Support for Intel Enterprise Digital Fence
- The Platform Discovery Utility can now discover these additional Intel products:
- Intel SSD Pro 2500 Series; Enterprise Digital Fence
- Intel Identity Protection Technology with One Time Password; Public Key Infrastructure; Multi Factor Authentication
- Intel Identity Protection Technology with Intel WiGig
- New Profile Editor and Profile Editor Plugin Interface
- New Required Permissions for Solutions Framework

Technical Specifications – Display Panel Specifications

DISPLAY PANEL SPECIFICATIONS**23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) non-touch or optional Projected Capacitive Touch supports up to 10 touch-points**

Non-Touch Support HW low blue light feature

Type	IPS WLED Backlit LCD
Active area (mm)	527.04 x 296.46
Native Resolution (HxV)	1920 x 1080
Refresh Rate	60 Hz @ 1920 x 1080
Aspect ratio	16:9
Pixel pitch (HxV)(mm)	0.2745 x 0.2745
Contrast ratio	1000:1
Brightness*	250nits
Viewing angle (HxV)	178 ° x 178 °
Backlight lamp life (to half brightness)	30,000 hours minimum
Color support	Up to 16.7 million colors with the use of FRC technology
Color gamut	NTSC 72%
Anti-glare	Yes*
Response Time	14ms
Default color temperature	Warm (6500K)

NOTE*: Actual brightness will be lower with touchscreen or HP Sure View**23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) with HP Sure View (optional)**

Type	IPS WLED Backlit LCD
Active area (mm)	527.04 x 296.46
Native Resolution (HxV)	1920 x 1080
Refresh Rate	60 Hz @ 1920 x 1080
Aspect ratio	16:9
Pixel pitch (HxV)(mm)	0.2745 x 0.2745
Contrast ratio	1000:1
Brightness*	285 nits (non-Privacy); 400 nits (Privacy)
Viewing angle (HxV)	178° x 178° (non-Privacy); 80° x 178° (Privacy)
Backlight lamp life (to half brightness)	30,000 hours minimum
Color support	Up to 16.7 million colors with the use of FRC technology
Color gamut	NTSC 72%
Anti-glare	Yes*
Response Time	14ms
Default color temperature	Warm (6500K)

NOTE*: Actual brightness will be lower with touchscreen or HP Sure View

Technical Specifications – Display Panel Specifications

27.0" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) non-touch

Support HW low blue light feature

Type	IPS WLED Backlit LCD
Active area (mm)	597.888 x 336.312
Native Resolution (HxV)	1920 x 1080
Refresh Rate	60 Hz @ 1920 x 1080
Aspect ratio	16:9
Pixel pitch (HxV)(mm)	0.3114 x 0.3114
Contrast ratio	1000:1
Brightness	250nits
Viewing angle (HxV)	178° x 178°
Backlight lamp life (to half brightness)	30,000 hours minimum
Color support	Up to 16.7 million colors with the use of FRC technology
Color gamut	NTSC 72%
Anti-glare	Yes*
Response Time	14ms
Default color temperature	Warm (6500K)

27.0" diagonal IPS widescreen WLED backlit LCD (2560 x 1440) Touch

Support HW low blue light feature

Type	IPS WLED Backlit LCD
Active area (mm)	596.736 x 335.664
Native Resolution (HxV)	2560 x 1440
Refresh Rate	60 Hz @ 2560 x 1440
Aspect ratio	16:9
Pixel pitch (HxV)(mm)	0.2331 x 0.2331
Contrast ratio	1000:1
Brightness*	250nits
Viewing angle (HxV)	178° x 178°
Backlight lamp life (to half brightness)	30,000 hours minimum
Color support	Up to 16.7 million colors
Color gamut	NTSC 72%
Anti-glare	No*
Response Time	14ms
Default color temperature	Warm (6500K)

1. All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

2. For All in One only Intel® HD Graphics (integrated)

NOTE*: Actual brightness will be lower with touchscreen or HP Sure View

Technical Specifications – Display Panel Specifications

Adjustable Height Stand:	Height - Vertical/Landscape Adjustment	130mm (±2 mm)
	Portrait Adjustment	No portrait
	Tilt Angle	-5° to +18° (±2°) in landscape and portrait
	Rotation (Swivel)	90° (±1°) (45 left, 45 right)
	Pivot	No pivot
Recline Stand:	Height - Vertical Adjustment	No height
	Tilt Angle	+36.5° to +58° (+/-1.5°)
	Rotation (swivel)	No swivel

Technical Specifications – Graphics

GRAPHICS

HP EliteDesk 800 G6 Desktop Mini Business PC

Intel® HD Graphics (integrated)

VGA Controller

Integrated

DisplayPort™

Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays connected to any output controlled by Intel® Graphics

HDMI (optional)

Supports HDMI 2.0a features

Supports HDCP 2.3

Supports audio over HDMI

VGA (optional)

VGA output

USB-C® DP Alt Mode (optional)

DisplayPort over the optional USB-C® module

Memory

The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.

Maximum Color Depth

up to 10 bits/color

HEVC 10b Enc/Dec HW

VP9 10b Dec HW

Graphics/Video API Support

HDR

Rec. 2020

DX12

Max. Resolution (VGA)

2048 x 1536@60Hz

Max. Resolution (HDMI)

4096 x 2160@60Hz

Max. Resolution (DP)

4096 x 2160@60Hz

Nvidia® GeForce® GTX1660 Ti

Architecture

Discrete GPU

Nvidia® GPU drives the integrated panel and all of the graphics output ports

DisplayPort

Maximum pixel clock:1.3 GHz pixels per second

Maximum bandwidth:25.92 Gbps per connector (FEC Disable)

HDMI

Supports HDMI 2.0 features

Supports HDCP 2.2, HDR

Memory

6GByte, 192bit wide GDDR6

Maximum Color Depth

up to 12 bits/color

Graphics/Video API Support

DirectX 12

OpenGL 4.6

Display Port

Support DP1.4(DSC1.2a)

Maximum pixel clock:1.3 GHz pixels per second

Maximum bandwidth:25.92 Gbps per connector (FEC Disable)

Max. Resolution (HDMI)

4096 x 2160@60Hz

Max. Resolution (DP)

5120 x 3200@60Hz Example of maximum resolutions with CVT-RB timings

Port Availability

(3) Mini DP 1.4 ports and (1) Micro HDMI 2.0 port

Technical Specifications – Graphics

HP EliteDesk 800 G6 Tower Business PC

Intel® UHD Graphics (integrated)

VGA Controller	Integrated
DisplayPort™ 1.4	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays connected to any output controlled by Intel® Graphics
HDMI (optional)	Supports HDMI 2.0a features
VGA (optional)	Supports HDCP 2.2
USB-C® DP Alt Mode (optional)	Supports BT2020 and HDR playback (7th Gen processors only)
Memory	VGA output
Maximum Color Depth	DisplayPort over the optional USB-C® module
Graphics/Video API Support	The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
34" UHD Supported Resolutions and Refresh Rates. Other resolutions may also work.	up to 10 bits/color
Max. Resolution (VGA)	HEVC 10b Enc/Dec HW
Max. Resolution (HDMI)	VP9 10b Dec HW
Max. Resolution (DP)	HDR
	Rec. 2020
	DX12
	640x480 60 Hz
	640x480 67Hz
	640x480 72Hz
	640x480 75Hz
	720x400 70Hz
	800x600 60Hz
	800x600 75Hz
	1024x768 60Hz
	1024x768 75Hz
	1280x960 60Hz
	1280x720 60Hz
	1280x1024 60Hz
	1280x1024 75Hz
	1440x900 60Hz
	1440x900 75Hz
	1680x1050 60Hz
	1920x1080 60Hz
	3440x1440 60Hz (Native Resolution)
	3440x1440 30Hz

NVIDIA® GeForce® RTX 2060 Super 8GB Graphics Card

Engine Clock	1650 MHz
Memory Clock	7000 MHz
Memory Size(width)	8 GB(256-bit)
Memory Type	256M x 32 GDDR6
Max. Resolution(DVI)	2560x1600@60Hz
Max. Resolution(HDMI)	4096x2160@60Hz
Max. Resolution(DP)	7680x4320@60Hz
Multi Display Support	3 displays
HDCP Compliance	Yes

Technical Specifications – Graphics

Rear I/O connectors(bracket)	DVI+HDMI+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<175W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

AMD® Radeon™ RX 550X 4 GB FH PCIe x16

Engine Clock	1183MHz
Memory Clock	6 Gbps
Memory Size(width)	4 GB(128-bit)
Memory Type	GDDR5
Max. Resolution(HDMI)	4096x2160 @ 60Hz
Max. Resolution(DP)	5120x2880 @ 60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	HDMI, DPx2
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP (low profile) PCB with FH/LP bracket

AMD® Radeon™ RX 580 8GB GDDR5 Graphics Card

Engine Clock	1266 MHz
Memory Clock	4000 MHz
Memory Size(width)	8 GB (256-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(HDMI)	4096x2160@60Hz
Max. Resolution(DP)	5120x3200@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	HDMI + DPx3
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<150W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® GeForce® RTX 2080 Super 8GB GDDR6

Engine Clock	1815 MHz
Memory Clock	7750 MHz
Memory Size(width)	8GB (256-bit)
Memory Type	256M x 32 GDDR6
Max. Resolution(Virtual Link)	3840 x 2160@60Hz
Max. Resolution(HDMI)	4096 x 2160@60Hz
Max. Resolution(DP)	7680 x 4320@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	DPx3 + HDMI + Virtual Link

Technical Specifications – Graphics

Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<285W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® GeForce® RTX 2070 Super 8GB GDDR6

Engine Clock	1620 MHz
Memory Clock	7000 MHz
Memory Size(width)	8GB (256-bit)
Memory Type	256M x 32 GDDR6
Max. Resolution(Virtual Link)	3840 x 2160@60Hz
Max. Resolution(HDMI)	4096 x 2160@60Hz
Max. Resolution(DP)	7680 x 4320@60Hz
HDCP Compliance	Yes
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<210W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® Quadro P620 2GB Graphics Card

Engine Clock	1354 MHz
Memory Clock	2500 MHz
Memory Size(width)	2GB (128-bit)
Memory Type	128M x 32 GDDR5
Max. Resolution(DP)	5120x2880@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	mDPx4
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<40W
PCB form-factor with bracket	LP PCB with LP bracket

NVIDIA® Quadro P400 2GB Graphics Card

Engine Clock	1252 MHz
Memory Clock	2000 MHz
Memory Size(width)	2GB (64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(DP)	5120x2880@60Hz
Multi Display Support	3 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	mDPx3
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<30W
PCB form-factor with bracket	LP PCB with LP bracket

Technical Specifications – Graphics

AMD® Radeon™ R7 430 2GB VGA+DP 64bit Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	2 GB(64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(HDMI)	2048x1536
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	VGA+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

AMD® Radeon™ R7 430 2GB GDDR5 2DP 64 bit Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	2 GB(64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	yes
Rear I/O connectors(bracket)	DPx2
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

HP EliteDesk 800 G6 Small Form Factor Business PC

Intel® HD Graphics (integrated)

VGA Controller	Integrated
DisplayPort™ 1.4	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays connected to any output controlled by Intel® Graphics
HDMI (optional)	Supports HDMI 2.0a features Supports HDCP 2.2 Supports audio over HDMI
VGA (optional)	VGA Output
USB-C® DP Alt Mode (optional)	DisplayPort over the optional USB-C® module
Memory	The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Color Depth	up to 10 bits/color
Graphics/Video API Support	HEVC 10b Enc/Dec HW VP9 10b Dec HW HDR Rec. 2020 DX12
Max. Resolution (VGA)	2048 x 1536@60Hz
Max. Resolution (HDMI)	4096 x 2160@60Hz

Technical Specifications – Graphics

Max. Resolution (DP) 4096 x 2160@60Hz

AMD® Radeon™ R7 430 2GB VGA+DP 64bit Graphics Card

Engine Clock 780 MHz
Memory Clock 1100 MHz
Memory Size(width) 1 GB(64-bit)
Memory Type 256M x 32 GDDR5
Max. Resolution(HDMI) 2048x1536
Max. Resolution(DP) 4096x2160@60Hz
Multi Display Support 2 displays
HDCP Compliance Yes
Rear I/O connectors(bracket) VGA+DP
Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W) <50W
PCB form-factor with bracket LP PCB with FH/LP bracket

AMD® Radeon™ R7 430 2GB GDDR5 2DP 64 bit Graphics Card

Engine Clock 780 MHz
Memory Clock 1100 MHz
Memory Size(width) 1 GB(64-bit)
Memory Type 256M x 32 GDDR5
Max. Resolution(DP) 4096x2160@60Hz
Multi Display Support 2 displays
HDCP Compliance yes
Rear I/O connectors(bracket) DPx2
Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W) <50W
PCB form-factor with bracket LP PCB with FH/LP bracket

AMD® Radeon™ RX550 4 GB PCIe x16

Engine Clock 1183MHz
Memory Clock 6 Gbps
Memory Size(width) 4 GB(128-bit)
Memory Type GDDR5
Max. Resolution(HDMI) 4096x2160 @ 60Hz
Max. Resolution(DP) 5120x2880 @ 60Hz
Multi Display Support 2 displays
HDCP Compliance Yes
Rear I/O connectors(bracket) HDMI, DP
Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W) <50W
PCB form-factor with bracket LP (low profile) PCB with FH/LP bracket

Technical Specifications – Graphics

AMD Radeon™ 520 1GB Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	1 GB (32-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(DP)	2048x1536@60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	VGA+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

Technical Specifications – Graphics

HP EliteOne 800 G6 23.8-in All-in-One

Intel® UHD Graphics (integrated)

VGA Controller	Integrated
DisplayPort™ 1.4	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays (including the integrated panel and all attached displays)
HDMI-in	Support HDMI-In
Memory	The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Color Depth	up to 10 bits/color HEVC 10b Enc/Dec HW VP9 10b Dec HW
Graphics/Video API Support	HDR Rec. 2020 DX12
Max. Resolution (VGA)	2048 x 1536@60Hz
Max. Resolution (HDMI)	4096 x 2160@60Hz
Max. Resolution (DP)	4096 x 2160@60Hz

AMD® R19M

Architecture	Discrete GPU AMD® GPU drives the integrated panel and all of the graphics output ports
DisplayPort	Multimode capable; supports HDCP, HDR, Display Port Audio (6 streams max), DisplayPort HBR3 link rates and Multi-Stream Technology for a maximum of 5 3 displays (including the integrated panel and all attached displays)
HDMI-In	Support HDMI-In
Memory	3GByte, 128bit wide GDDR6
Maximum Color Depth	up to 12 bits/color
Graphics/Video API Support	DirectX 12 OpenCL 2.0 OpenGL 4.5 AMD® Unified Video Decoder (UVD)
Max. Resolution (DP)	4096 x 2160@60Hz

Nvidia® N18E-G2R

Architecture	Discrete GPU NVidia® GPU drives the integrated panel and all of the graphics output ports
DisplayPort	Multimode capable; supports HDCP, HDR, Display Port Audio (6 streams max), DisplayPort HBR3 link rates and Multi-Stream Technology for a maximum of 3 displays (including the integrated panel and all attached displays)
HDMI-In	Support HDMI-In
Memory	8GByte, 128bit wide GDDR6
Maximum Color Depth	up to 12 bits/color
Graphics/Video API Support	DirectX 12 OpenCL 2.0 OpenGL 4.5
Max. Resolution (DP)	4096 x 2160@60Hz

Technical Specifications – Storage

STORAGE**500GB 7200RPM 3.5in SATA HDD**

Capacity	500GB
Rotational Speed	7,200 rpm
Interface	SATA 6.0 Gb/s
Buffer Size	32MB
Logical Blocks	976,773,168
Seek Time	11 ms (Average)
Height	1 in/2.54cm
Width	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1TB 7200RPM 3.5in SATA HDD

Capacity	1TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	64MB
Logical Blocks	1,953,525,168
Seek Time	11 ms (Average)
Height	1 in/2.54cm
Width (nominal)	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2TB 7200RPM 3.5in SATA HDD

Capacity	2TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	64MB
Logical Blocks	3,907,050,336
Seek Time	11 ms (Average)
Height	1.028in/26.11mm
Width (nominal)	Media diameter: 3.5 in/88.9 mm Physical size: 4 in/102 mm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications – Storage

500GB 7200RPM 2.5in SATA HDD

Capacity	500GB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	Up to 128MB
Logical Blocks	976,773,168
Seek Time	12 ms (Average)
Height	0.283in/7.2mm (Max.)
Width (nominal)	2.75in/70mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1TB 7200RPM 2.5in SATA HDD

Capacity	1TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	Up to 128MB
Logical Blocks	1,953,525,168
Seek Time	12 ms (Average)
Height	0.283in/7.2mm (Max)
Width (nominal)	2.75in/70mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2TB 5400RPM 2.5in SATA HDD

Capacity	2TB
Rotational Speed	5,400 rpm
Interface	SATA 6 Gb/s
Buffer Size	128MB
Logical Blocks	3,907,050,336
Seek Time	12 ms (Average)
Height	0.374in/9.5mm (nominal)
Width (nominal)	2.75in/70mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications – Storage

500GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD

Capacity	500GB
Architecture	Self-Encrypting (SED) Solid State Drive with SATA interface
Interface	SATA 6 Gb/s
Buffer Size	128 MB
Logical Blocks	976,773,168
Seek Time	12 ms (Average)
Height	0.283in/7.2mm (nominal)
Width	2.75in/70mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD

Capacity	500GB
Architecture	Self-Encrypting (SED) Solid State Drive with SATA interface
Interface	SATA 6 Gb/s
Buffer Size	128 MB
Logical Blocks	976,773,168
Seek Time	12 ms (Average)
Height	0.283in/7.2mm (nominal)
Width	2.75in/70mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 780MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications – Storage

512GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 860MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	128GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 2800MB/s
Maximum Sequential Write	Up to 600MB/s
Logical Blocks	250,069,680
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications – Storage

512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	1TB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 3480MB/s
Maximum Sequential Write	Up to 3037MB/s
Logical Blocks	2,000,409,264
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	2TB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 3500MB/s
Maximum Sequential Write	Up to 3000MB/s
Logical Blocks	3,907,029,168
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications – Storage

256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB Intel® PCIe® NVMe™ QLC + 16GB Intel® Optane™

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 1450MB/s
Maximum Sequential Write	Up to 500MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications – Storage

512GB Intel® PCIe® NVMe™ QLC + 32 GB Intel® Optane™

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 2400MB/s
Maximum Sequential Write	Up to 1300MB/s
Logical Blocks	1,000,215,215
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP 9.5mm Slim DVD-ROM Drive

Height	9.5 mm height
Orientation	Either horizontal or vertical
Interface type	SATA/ATAPI
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel
Weight (max)	Up to 0.31 lb (140g) without bezel
Read Speeds	DVD+R/-R/+RW/ -RW/+R DL /-R DL Up to 8X DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X CD-RW Up to 24X
Access time (typical reads, including settling)	Random: DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full stroke: DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim DVD Writer Drive

Height	9.5 mm height
Orientation	Either horizontal or vertical
Interface type	SATA/ATAPI
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB standard
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel
Weight (max)	0.31 lb (140 g)
Write Speeds	DVD-R DL - Up to 6X DVD+R - Up to 8X DVD+RW - Up to 8X

Technical Specifications – Storage

	DVD+R DL - Up to 6X DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X DVD-RW, DVD+RW - Up to 8X
Read Speeds	DVD-R DL, DVD+R DL - Up to 8X DVD+R, DVD-R - Up to 8X DVD-ROM DL, DVD-ROM - Up to 8X CD-ROM, CD-R - Up to 24X CD-RW - Up to 24X
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim Blu-Ray Writer Drive

Height	9.5 mm height
Orientation	Either horizontal or vertical
Interface type	SATA/ATAPI
Disc recording capacity	Up to 128 GB QL, 100 GB TL, 50 GB DL or 25 GB standard SL
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel
Weight (max)	0.29 lb (132 g)
Write Speeds	BD-R SL/DL Up to 6X BD-R TL/QL Up to 4X BD-R Up to 6X BD-RE Up to 2X DVD-R Up to 8X DVD-R DL - Up to 6X DVD-RW Up to 6X DVD+R Up to 8X DVD+R DL - Up to 6X DVD+RW Up to 8X DVD-RAM Up to 5X CD-R Up to 24X CD-RW Up to 10X
Read Speeds	BD-ROM Up to 6X BD-R Up to 6X BD-RE SL/DL Up to 6X BD-RE TL Up to 4X DVD-ROM Up to 8X DVD-R SL/DL Up to 8X DVD-R Up to 8X DVD-RW Up to 8X DVD+R SL/DL Up to 8X DVD+R Up to 8X DVD+RW Up to 8X

Technical Specifications – Storage

BDMV (AACs Compliant Disc)
Up to 6x/2x (Read/Play)
DVD-RAM Up to 5x
DVD-Video (CSS Compliant Disc)
Up to 8x/4x (Read/Play)
CD-R/RW/ROM Up to 24x
CD-DA (DAE) Up to 24X/10X (Read/Play)

Access time (typical reads, including settling)

Random BD-ROM: 205 ms (typical), DVD-ROM: 185 ms (typical),
CD-ROM: 165 ms (typical)
Full Stroke BD-ROM: 350 ms (typical), DVD-ROM: 345 ms (typical),
CD-ROM: 340 ms (typical)

Power

Source Slimline SATA DC power receptacle
DC Power Requirement 5 VDC \pm 5%-100 mV ripple p-p
DC Current 5 VDC -1200 mA typical, 2000 mA maximum

Environmental conditions (operating - non-condensing)

Temperature 41° to 122° F (5° to 50° C)
Relative Humidity 10% to 80%
Maximum Wet Bulb Temperature 84° F (29° C)

NETWORKING AND COMMUNICATIONS

Intel® I219-LM 1 Gigabit Network Connection LOM (vPro)	
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling (Hash Mode Only) Jumbo Frame 9K
Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel® vPro® support with appropriate Intel® chipset components

Technical Specifications – Networking and Communications

Intel® I225-LM 2.5 Gigabit Network Connection LOM (non-vPro)	
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	<ol style="list-style-type: none"> 1. 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 2. 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 3. 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40) 4. 2.5 Gbit/s operation(2.5GBASE-T; IEEE 802.3bz Clause 126) 5. Auto-Negotiation (Automatic Speed Selection) <p>Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 & 1000 Mbit/s</p>
IEEE Compliance	<p>IEEE 802.1p QoS (Quality of Service) Support</p> <p>IEEE 802.1q VLAN support</p> <p>IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)</p> <p>IEEE 802.3az EEE (Energy Efficient Ethernet)</p> <p>IEEE 802.3i 10BASE-T</p> <p>IEEE 802.3u 100BASE-TX</p> <p>IEEE 802.3ab 1000BAE-T</p> <p>IEEE 802.3bz 2.5GBASE-T</p>
Performance	<p>TCP/IP/UDP Checksum Offload (configurable)</p> <p>Protocol Offload (ARP & NS)</p> <p>Large send offload and Giant send offload</p> <p>Receiving Side Scaling</p> <p>Jumbo Frame 9K</p>
Power consumption	<p>Cable Disconnection: 25mW</p> <p>100Mbps Full Run: 450mW</p> <p>1000bp Full Run: 1000mW</p> <p>WoL Enable(S3/S4/S5): 50mW</p> <p>WoL Disable(S3/S4/S5): 25mW</p>
Power Management	<p>ACPI compliant – multiple power modes</p> <p>Situation-sensitive features reduce power consumption</p> <p>Advanced link down power saving for reducing link down power consumption</p>
Management Interface	Auto MDI/MDIX Crossover cable detection

Technical Specifications – Networking and Communications

IT Manageability	<p>Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)</p> <p>PXE 2.1 Remote Boot</p> <p>Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))</p> <p>Comprehensive diagnostic and configuration software suite</p> <p>Virtual Cable Doctor for Ethernet cable status</p>
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel® i210 10/100/1000 NIC	
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	<p>10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)</p> <p>100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)</p> <p>1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)</p> <p>Auto-Negotiation (Automatic Speed Selection)</p> <p>Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s</p>
IEEE Compliance	<p>IEEE 802.1p QoS (Quality of Service) Support</p> <p>IEEE 802.1q VLAN support</p> <p>IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)</p> <p>IEEE 802.3az EEE (Energy Efficient Ethernet)</p>
Performance	<p>TCP/IP/UDP Checksum Offload (configurable)</p> <p>Protocol Offload (ARP & NS)</p> <p>Large send offload and Giant send offload</p> <p>Receiving Side Scaling</p> <p>Jumbo Frame 9K</p>
Power consumption	<p>Cable Disconnection: 25mW</p> <p>100Mbps Full Run: 450mW</p> <p>1000bp Full Run: 1000mW</p> <p>WoL Enable(S3/S4/S5): 50mW</p> <p>WoL Disable(S3/S4/S5): 25mW</p>
Power Management	<p>ACPI compliant – multiple power modes</p> <p>Situation-sensitive features reduce power consumption</p> <p>Advanced link down power saving for reducing link down power consumption</p>
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)
Security & Manageability	PXE 2.1 Remote Boot

Technical Specifications – Networking and Communications

Intel Wi-Fi 6 AX201 + BT5.2 Wireless Card (802.11ax 2x2, vPro, supporting gigabit file transfer speeds) vPro	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Features Wi-Fi 6 technology
Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) • 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security³	• IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power²	• 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum • 802.11ax HT40(2.4GHz): +10dBm minimum • 802.11ax VHT160(5GHz): +10dBm minimum
Power Consumption	• Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated)

Technical Specifications – Networking and Communications

	<ul style="list-style-type: none"> • Idle mode: 50 mW (WLAN unassociated) • Connected Standby: 10mW • Radio disabled: 8 mW 	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity³	<ul style="list-style-type: none"> •802.11b, 1Mbps: -93.5dBm maximum •802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum •802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum 	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.8g 2. Type 126: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating	14° to 158° F (-10° to 70° C)
	Non-operating	-40° to 176° F (-40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)
Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED White – Radio ON	
HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Card Technology		
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1/5.2 Wireless Card Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels. Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +9.5 dBm for BR and EDR.	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW	
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software	
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	

Technical Specifications – Networking and Communications

Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel Wi-Fi 6 AX201 + BT5.2 Wireless Card (802.11ax 2x2, non-vPro, supporting gigabit file transfer speeds) non-vPro	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Features Wi-Fi 6 technology
Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) • 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)

Technical Specifications – Networking and Communications

Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM	
Security³	<ul style="list-style-type: none"> • IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI 	
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power²	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum • 802.11ax HT40(2.4GHz): +10dBm minimum • 802.11ax VHT160(5GHz): +10dBm minimum 	
Power Consumption	<ul style="list-style-type: none"> • Transmit mode 2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW 	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity³	<ul style="list-style-type: none"> • 802.11b, 1Mbps: -93.5dBm maximum • 802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum • 802.11ax, MCS11(HT40): -59dBm maximum • 802.11ax, MCS11(VHT160): -58.5dBm maximum 	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.8g 2. Type 126: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating	14° to 158° F (-10° to 70° C)
	Non-operating	-40° to 176° F (-40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)

Technical Specifications – Networking and Communications

Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED Off – Radio ON	
HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Card Technology		
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1/5.2 Wireless Card Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels. Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +9.5 dBm for BR and EDR.	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW	
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software	
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC60950 UL, CSA, and CE Mark	
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)	

Technical Specifications – Networking and Communications

Realtek RTL8822CE 802.11ac 2x2 Wi-Fi + BT5.0 Wireless Card	
Wireless LAN Standards	<ul style="list-style-type: none"> IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Wi-Fi® certified
Frequency Band	<ul style="list-style-type: none"> 802.11b/g/n <ul style="list-style-type: none"> • 2.402 – 2.482 GHz 802.11a/n/ac <ul style="list-style-type: none"> • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	<ul style="list-style-type: none"> • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security³	<ul style="list-style-type: none"> • IEEE and Wi-Fi® compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power²	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum
Power Consumption	<ul style="list-style-type: none"> • Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW

Technical Specifications – Networking and Communications

Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity³	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.8g 2. Type 1216: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating	14° to 158° F (-10° to 70° C)
	Non-operating	-40° to 176° F (-40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)
Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON	
HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0 Wireless Card Technology		
Bluetooth® Specification	4.0/4.1/4.2/5.0 Wireless Card Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW	
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software	
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark	

Technical Specifications – Networking and Communications

Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
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Technical Specifications – Input/Output Devices

I/O DEVICES

HP Wired Desktop 320K Keyboard		
Physical Characteristics	Keys	104, 105, 107, 109 layout (depending on country)
	Dimensions (L x W x H)	16.77 x 4.36 x 0.65 in (426.2 x 110.9 x 16.7 mm)
	Weight	14.57 oz (413g)
	Cable length	6 ft. (1.8 m)
Electrical	Operating voltage	5V
	Power consumption	50mA - 100 mA
	System interface	USB
Mechanical	Keycaps	Low-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Plunger
Environmental		
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 149° F (-30° to 65° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	0% to 90% (non-condensing at ambient)
Approvals	FCC, ICES, CULus, CE, GS, EAC, Ukraine, India BIS, KCC, RCM, BSMI, VCCI	
Ergonomic compliance	TUVGS	
Kit contents	Keyboard, QSP, Warranty Card, Product Notice	

HP USB Premium Keyboard		
Physical Characteristics	Keys	104, 105 layout (depending upon country)
	Dimensions (L x W x H)	17.04 x 5.55 x 0.52 in (433 x 141 x 13.2 mm)
	Weight	1.54 lb. (698g)
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	35mA (All LED on)
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
	Microsoft® PC 99 - 2001	Functionally compliant
Mechanical	Keycaps	Low-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback

Technical Specifications – Input/Output Devices

	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft. (1.8 m)
	Microsoft PC 99 - 2001	Mechanically compliant
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC	
Ergonomic compliance	TUVGS	
Kit contents	Keyboard, QSP	
Warranty Card	Product Notice	

HP Wired Desktop 320M Mouse		
Dimensions (H x L x W)	4.08 x 2.49 x 1.39 in (103.8 x 63.4 x 35.5 mm)	
Weight	2.67 oz (75.8 g)	
Mechanical	Connector	USB
	Resolution	1000 DPI
	Sensor	Optical Red Sensor
Tracking speed	Tracking acceleration	8G(max), 1G=9.8m/s ²
	Cable length	6 ft. (1.8 m)
	Color	Jack Black
Regulatory approvals	Compliant	FCC, ICES, CULus, CE, GS, EAC, Ukraine. India BIS, KCC, RCM, BSMI, VCCI

Technical Specifications – Input/Output Devices

HP USB Premium Mouse		
Dimensions (H x L x W)	4.21 x 2.64 x 1.52 in (107 x 67 x 38.7 mm)	
Weight	0.19lb (90g)	
Environmental	Operating temperature	50° to 122°F (10° to 50° C)
	Non-operating temperature	-22° to 140°F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	50 g, 6 surfaces
	Non-operating shock	80 g, 6 surfaces
	Operating vibration	2 g peak acceleration
	Non-operating vibration	4 g peak acceleration
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	12mA
Mechanical	Connector	USB 2.0
	Type	3D mouse (3 keys and wheel)
	Resolution	800, 1200, 1600 DPI
	Sensor	Pixart PAN3606DL
Tracking speed	Tracking acceleration	8G(max), 1G=9.8m/s ²
	Cable length	6 ft. (1.8 m)
	Color	Jack Black
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC

HP USB Mouse		
Dimensions (H x L x W)	37mm x 115mm x 62.9mm	
Weight	90 +10g/- 5 g	
Color	Black	
Connector	USB	
Mechanical	Resolution	800 DPI sensitivity
	Buttons	Two primary buttons and clickable scroll wheel

Technical Specifications – Audio/Multimedia

AUDIO/MULTIMEDIA

HP EliteDesk 800 G6 Tower Business PC

Type	Integrated
HD Stereo Codec	Conexant CX20632 / Realtek ALC 3867
Audio I/O Ports	Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port 1 - Headphone port Rear: 1 - Line-out 1 - Line-in which is re-taskable as a Microphone Input All ports are 3.5mm and support stereo
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes

HP EliteDesk 800 G6 Small Form Factor Business PC

Type	Integrated
HD Stereo Codec	Conexant CX20632 / Realtek ALC 3867
Audio I/O Ports	Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port 1 - Headphone port Rear: 1 - Line-out 1 - Line-in which is re-taskable as a Microphone Input All ports are 3.5mm and support stereo
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes

Technical Specifications – Audio/Multimedia

HP EliteDesk 800 G6 Desktop Mini Business PC

Type	Integrated
HD Stereo Codec	Realtek ALC3205-CG / Realtek ALC 3867
Audio I/O Ports	combo audio jack with CTIA and headset support
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes

HP EliteOne 800 G6 24 & 27 All-in-One

Bang & Olufsen Audio

Type	Integrated
HD Stereo Codec	Realtek ALC3274
Audio I/O Ports	Side headset connector supports a CTIA/OMTP style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port Side headphone connector supports a headphone connections Rear line out connector All ports are 3.5mm and support stereo
Internal Speaker Amplifier	5W per channel class D stereo amplifier for the internal speakers only
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speakers.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes - Stereo

Technical Specifications – Integrated Webcam and Microphone

INTEGRATED WEBCAM AND MICROPHONE

Integrated Webcam and Microphone

Optional integrated 5 MP Full HD RGB webcam & microphone; maximum resolution of 2624 x 1976

Optional integrated 5 MP Full HD RGB dual-facing webcam with IR sensor (user-facing) & microphone; maximum resolution of 2624 x 1976

NOTE: All HP devices which carry the Bang & Olufsen brand are custom-tuned with Bang & Olufsen's acoustical engineers for precise sound experience in business use.

INTEGRATED FINGERPRINT SENSOR

Sensor type: Touch

Fingerprint matching: Performed on device

Anti-Spoofing: Yes

Windows Hello Support: Yes

Encryption: On sensor

FIPS Compliant: No

Technical Specifications – Power

POWER

HP EliteDesk 800 G6 Tower Business PC

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 95% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 SFF Business PC

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 95% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 Desktop Mini Business PC (35W)

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 Desktop Mini Business PC (65W)

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 Desktop Mini Business PC (125W)

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

Technical Specifications – Power

HP EliteOne 800 G6 24 & 27 All-in-One

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~45°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

	DM	SFF	TWR	AiO
External Power Supplies	65W EPS, 88% average efficiency at 115V & 89% at 230Vac 90W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac 150W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac	N/A	N/A	N/A
80 PLUS Gold	N/A	N/A	N/A	N/A
80 PLUS Platinum	N/A	350W active PFC / 80 PLUS Platinum 260W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	550W active PFC / 80 PLUS Platinum 350W active PFC / 80 PLUS Platinum 260W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	210W active PFC / 80 PLUS Platinum 280W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)
Operating Voltage Range	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac
Rated Line Frequency	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ
Operating Line Frequency	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ
Rated Input Current				
Rated Input Current with Energy Efficient* Power Supply	65W ≤ 1.6A 90W ≤ 1.7A 150W ≤ 2.5A	260W Platinum ≤ 3.1A 350W Platinum ≤ 4A	260W Platinum ≤ 3.1A 350W Platinum ≤ 4.2A 550W Platinum ≤ 6.6A	210W ≤ 2.8A 280W ≤ 3.2A
DC Output	+19.5V	+12V	+12V	+20V

Technical Specifications – Power

	DM	SFF	TWR	AiO
Current Leakage (NFPA 99: 2012)	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Power Supply Fan	N/A	70mm variable speed	70mm variable speed	N/A
Power cord length	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)
External Power Adapter	External power supply	Internal power supply	Internal power supply	Internal power supply
Dimensions	65W: 90 x 51 x 28.5mm & 102 x 55 x 30mm 90W: 126 x 50 x 30mm 150W: 148 x 75.5 x 25.4mm	165 x 95 x 73mm	165 x 95 x 73mm	110 x 110 x 26mm
Total Cord Length	6.0 ft. (1.83m)	6.0 ft. (1.83m)	6.0 ft. (1.83m)	6.0 ft. (1.83m)

Technical Specifications – Power

The power supply shall comply with harmonic input current requirements as detailed in EN61000-3-2 and JEIDA MITI standards. The harmonic input current requirements must be met under the following operating conditions:

Load Requirements: 50% and 100%

Input Voltage: 230Vac/50Hz.

For active power factor correction the power factor at 50% & 100% loads shall be greater than 0.9 over the entire nominal input voltage range (100-127VAC and 200-240VAC).

Condition	Standard Efficiency	82/85/82%	85/88/85%	87/90/87%	90/92/89%	Input Voltage
10% of Rated Load	-	75%	81%	84%	86%	115Vac/60HZ
20% of Rated Load	-	82%	85%	87%	90%	115Vac/60HZ
50% of Rated Load	-	85%	88%	90%	92%	115Vac/60HZ
	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.95	
100% of Rated Load	70%	82%	85%	87%	89%	115Vac/60HZ
	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.9	230Vac/50HZ

Technical Specifications – Weights and Dimensions

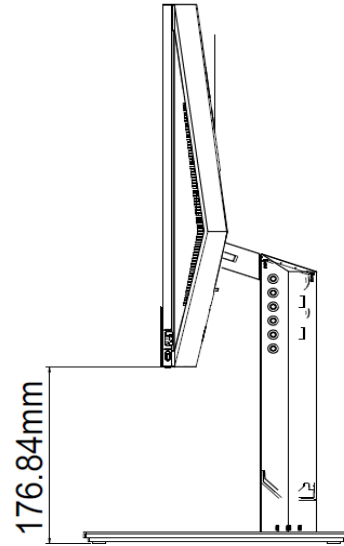
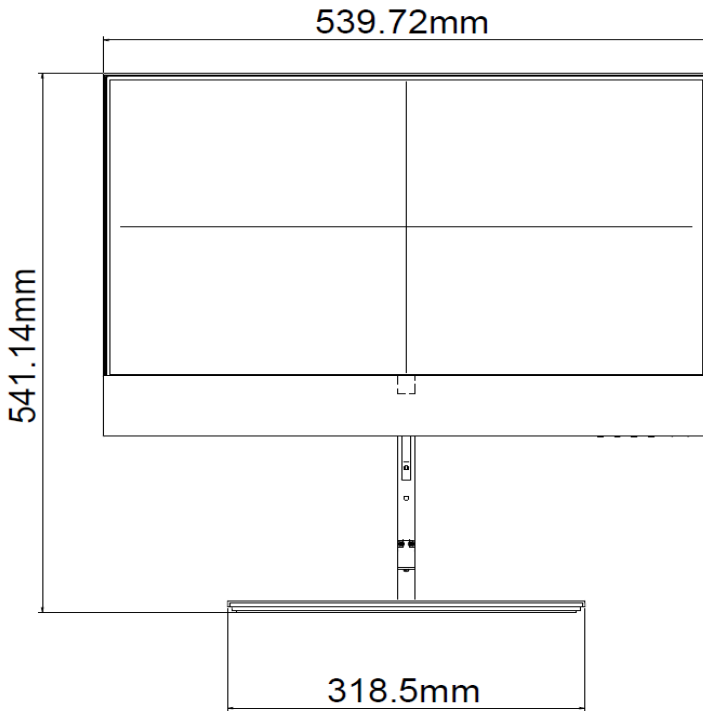
WEIGHTS & DIMENSIONS

	DM	SFF	TWR	AiO
Chassis (W x D x H)	6.97 x 6.89 x 1.35 in 177 x 175 x 34 mm	13.3 x 12.13 x 3.94in 338 x 308 x 100 mm	14.57 x 12.13 x 6.61in 370 x 308 x 165 mm	See table below.
System Volume	63.4 cu in 1.05 L	634.6 cu in 10.4 L	1168.21 cu in 18.8 L	See table below.
System Weight	3.13 lb 1.42 kg	13.5 lb 6.13 kg	21.74 lb 9.86 kg	See table below.
Max Supported Weight (desktop orientation)	0	77 lb 35 kg	77 lb 35 kg	See table below.
Stand Dimensions	160 x 117 x 18.5 mm	151.8 x 200 x 37.2 mm	N/A	See table below.
Packaging (W x D x H)	19.6 x 9.3 x 5.2 in 498 x 235 x 132 mm	15.71 x 19.65 x 9.06 in 399 x 499 x 230 mm	19.65 x 11.61 x 18.62 in 499 x 295 x 473 mm	See table below.
Shipping Weight	2.95 kg 6.49 lb	7.683 kg 16.92 lb	9.058 kg 19.95 lb	See table below.
Multipack Packaging (10 units)	20.28 x 16.54 x 25in 515 x 420 x 63 mm			
Palletization Profile	10 units per layer 17 layers max 170 units per pallet 46.3 x 39.2 x 94.1in, 1175 x 996 x 2389 mm (include pallet)	6 units per layer 10 layers max 60 units per pallet 1200 x 1000 x 2438 mm (include the pallet)	8 units per layer 5 layers ax 40 units per pallet 1200 x 1000 x 2495 mm (include the pallet)	10-units per layer 4-layers max 40-units per pallet (sea) 1200 x 1000 x 2470 mm

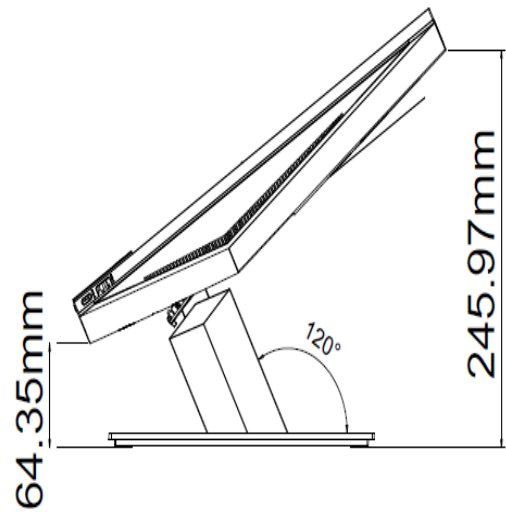
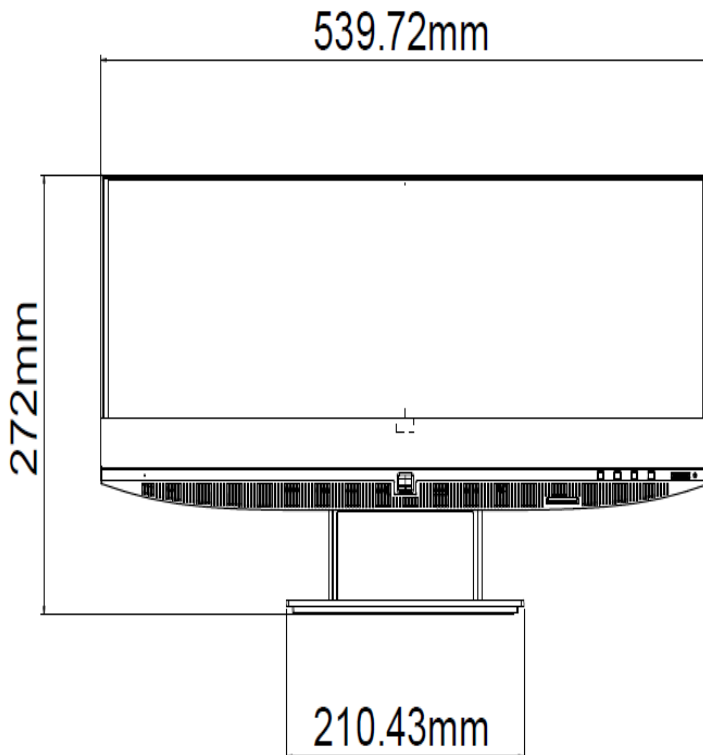
Technical Specifications – Weights and Dimensions

STANDS AND DIMENSIONS

HP EliteOne G6 AIO Adjustable Height Stand – 23.8"

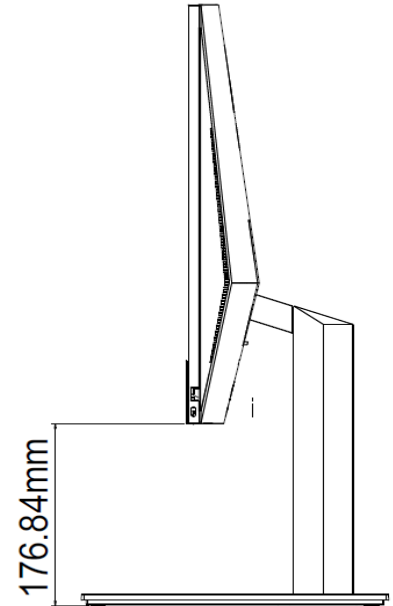
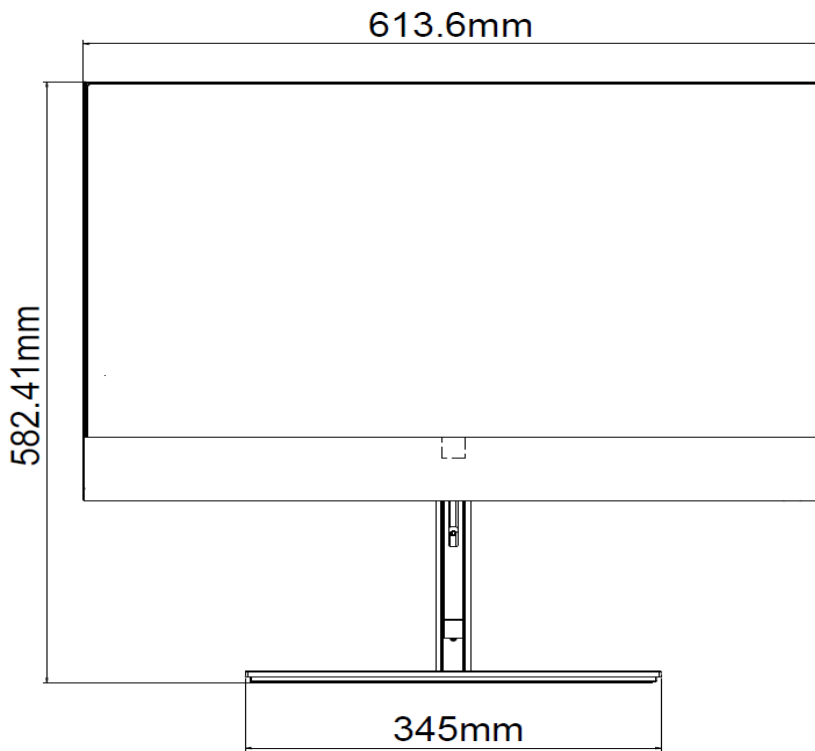


HP EliteOne G6 AIO Recline Stand – 23.8"

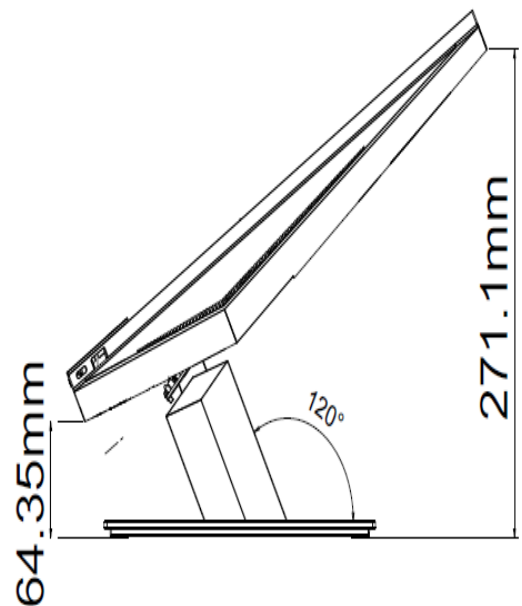
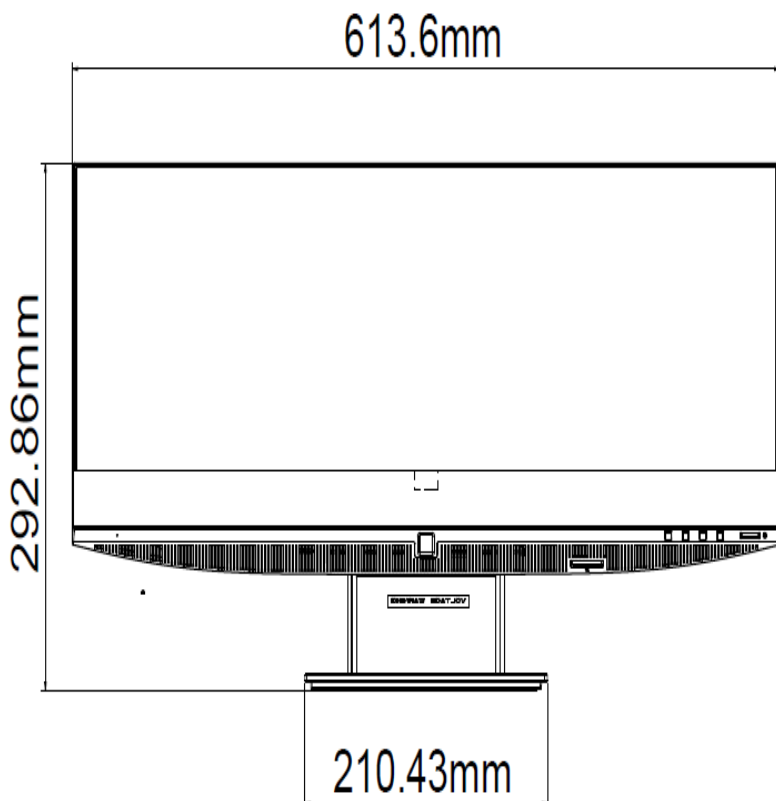


Technical Specifications – Weights and Dimensions

HP EliteOne G6 AIO Adjustable Height Stand – 27"



HP EliteOne G6 AIO Recline Stand – 27"



Technical Specifications – Weights and Dimensions

Adjustable Height Stand:	Height - Vertical/Landscape Adjustment	130mm (±2 mm)
	Portrait Adjustment	No portrait
	Tilt Angle	-5° to +18° (±2°) in landscape and portrait
	Rotation (Swivel)	90° (±1°) (45 left, 45 right)
	Pivot	No pivot

Recline Stand:	Height - Vertical Adjustment	No height
	Tilt Angle	+36.5° to +58° (+/-1.5°)
	Rotation (swivel)	No swivel

Technical Specifications – Weights and Dimensions

ALL-IN-ONE WEIGHTS AND DIMENSIONS

Weight without Touch Panel – 23.8”

Product Weight Unboxed	Without Stand 15.12 lbs. 6.86 kg	Adjustable Height Stand 20.46 lbs. 9.28 kg	Recline Stand 18.83 lbs. 8.54 Kg
Shipping Weight Boxed	Without Stand 19.51 lbs. 8.85 kg	Adjustable Height Stand 24.85 lbs. 11.27 kg	Recline Stand 23.08 lbs. 10.47 kg
Shipping Weight Pallet (30 units)	Without Stand 623.7 lbs. 283.5 kg	Adjustable Height Stand 783.4 lbs. 356.1 kg	Recline Stand 730.62 lbs. 332.1 kg

Weight with Touch Panel – 23.8”

Product Weight Unboxed	Without Stand 17.50 lbs. 7.94 kg	Adjustable Height Stand 22.84 lbs. 10.36 kg	Recline Stand 21.21 lbs. 9.62 Kg
Shipping Weight Boxed	Without Stand 21.89 lbs. 9.93 kg	Adjustable Height Stand 27.23 lbs. 12.35kg	Recline Stand 25.46 lbs. 11.55 kg
Shipping Weight Pallet (30 units)	Without Stand 694.98 lbs. 315.9 kg	Adjustable Height Stand 854.7lbs. 388.5kg	Recline Stand 801.9lbs. 364.5 kg

Dimensions (W x D x H) – 23.8”

Product Dimensions (Non-touch)	Without Stand 539.72 x 364.3 x 57.3 mm	Adjustable Height Stand (-5 ~ 20) degrees 539.72 x 541.14 x 236.98 mm	Recline Stand (30 ~ 60) degrees 539.72 x 379.44 x 209.35 mm
Product Dimensions (Sure View/ In-cell Touch)	Without Stand 539.72 x 364.3 x 59.3 mm	Adjustable Height Stand (-5 ~ 20) degrees 539.72 x 541.14 x 236.98 mm	Recline Stand (30 ~ 60) degrees 539.72 x 379.44 x 211.35 mm

Shipping Dimensions – 23.8”

Shipping Dimensions Boxed	Without Stand 628 x 186 x 635 mm	Adjustable Height Stand 628 x 186 x 635 mm	Recline Stand 628 x 186 x 635 mm
Shipping Dimensions Pallet Pallet (40 units)	Without Stand 1180 x 874 x 2060 mm	Adjustable Height 1180 x 874 x 2060 mm	Recline Stand 1180 x 874 x 2060 mm

Technical Specifications – Weights and Dimensions

Weight with Touch Panel – 27”

Product Weight Unboxed	Without Stand 19.56 lbs. 8.87 kg	Adjustable Height Stand 25.40 lbs. 11.52 kg	Recline Stand 23.26 lbs. 10.55 Kg
Shipping Weight Boxed	Without Stand 25.46 lbs. 11.55 kg	Adjustable Height Stand 31.31 lbs. 14.2 kg	Recline Stand 29.17 lbs. 13.23 kg
Shipping Weight Pallet (18 units)	Without Stand 496.98 lbs. 225.9 kg	Adjustable Height Stand 601.92 lbs. 273.6 kg	Recline Stand 563.5 lbs. 256.14 kg

Weight without Touch Panel – 27”

Product Weight Unboxed	Without Stand 17.79 lbs. 8.07 kg	Adjustable Height Stand 23.63 lbs. 10.72 kg	Recline Stand 21.50 lbs. 9.75 Kg
Shipping Weight Boxed	Without Stand 23.70 lbs. 10.75 kg	Adjustable Height Stand 29.54 lbs. 13.4 kg	Recline Stand 27.40 lbs. 12.43 kg
Shipping Weight Pallet (18 units)	Without Stand 465.3 lbs. 211.5 kg	Adjustable Height Stand 570.24 lbs. 259.2 kg	Recline Stand 531.83 lbs. 241.74 kg

Dimensions (W x D x H) – 27”

Product Dimensions (FHD)	Without Stand 613.6 x 405.57 x 58.7 mm	Adjustable Height Stand (-5 ~ 20) degrees 613.6 x 582.41 x 254.98 mm	Recline Stand (30 ~ 60) degrees 613.6 x 420.71 x 210.68 mm
Product Dimensions (QHD)	Without Stand 613.6 x 405.57 x 59.07 mm	Adjustable Height Stand (-5 ~ 20) degrees 613.6 x 582.41 x 254.98 mm	Recline Stand (30 ~ 60) degrees 613.6 x 420.71 x 211.05 mm

Shipping Dimensions – 27”

Shipping Dimensions Boxed	Without Stand 742 x 237 x 640 mm	Adjustable Height Stand 742 x 237 x 640 mm	Recline Stand 742 x 237 x 640 mm
Shipping Dimensions Pallet (18 units)	Without Stand 1180 x 958 x 2076 mm	Adjustable Height 1180 x 958 x 2076 mm	Recline Stand 1180 x 958 x 2076 mm

Technical Specifications – Miscellaneous Features

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode. Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel® Wired for Management support; industry wide initiative to make Intel® architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
 - Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initially):
 - 2 red + 2 white User must provide file for BIOS recovery (USB storage typically)
 - 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
 - 2 red + 4 white BIOS recovery is in progress
 - 3 red + 2 white Memory could not be initialized
 - 3 red + 3 white Graphics adaptor could not be found
 - 3 red + 4 white Power supply failure / not connected
 - 3 red + 5 white Processor not installed
 - 3 red + 6 white Current processor does not support an enabled feature
 - 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
 - 4 red + 3 white System internal temperature has exceeded its threshold
 - 5 red + 2 white System controller firmware is not valid
 - 5 red + 3 white System controller detected BIOS is not executing
 - 5 red + 4 white BIOS could not complete initialization / PCA failure
 - 5 red + 5 white System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:
 - This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- Flash Recovery with Video Configuration Record Software
- Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED - To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal (For MT, SFF, and DM only)
- Green Pull Tabs, and Quick Release Latches for easy Identification

Technical Specifications – Miscellaneous Features

Additional Features

Tower Orientation

Description

Product can be oriented as either a desktop (horizontal) or a tower (vertical) for MT, SFF, and DM only. SFF/DM requires optional stand.

Drive Lock

Implementation of the industry standard ATA Security feature set. When enabled, it prevents software access to user data on the drive until one or two user-defined passwords are provided.

Boot Sectors Protection

MBR and GPT sectors of the hard drive are critical to booting the operating system. By saving the MBR or GPT data (depending on the how the OS was installed), the BIOS will be able to monitor for changes and allow the user to override them with the backup copy at boot-up.

Drive Protection System

DPS Access through F10 Setup during Boot (for SATA hard drive only)

A diagnostic hard drive self- test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user

Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be replaced

The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types of failures

SMART Technology (Self-Monitoring, Analysis and Reporting Technology)

Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted

SMART I - Drive Failure Prediction

Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count

SMART II - Off-Line Data Collection

By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure

SMART III - Off-Line Read Scanning with Defect Reallocation

IOEDC: I/O Error Detection Circuitry

SMART IV - End-to-End CRC for hard drives

Detects errors in Read/Write buffers on HDD cache RAM

Technical Specifications – After Market Options

AFTER MARKET OPTIONS

Graphics Solutions	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
AMD® Radeon™ RX 550X 4GB Display Port Card		X			5LH79AA
AMD® Radeon™ R7 430 2GB 2 Display Port Card		X	X		5JW82AA
AMD® Radeon™ R7 430 2GB DP+VGA Card		X	X		5JW81AA

Desktop Mini Accessories	<u>DM</u>	<u>SFF</u>	<u>MT</u>	<u>AiO</u>	<u>Part Number</u>
HP Desktop Mini Port Cover v3	X (125W and discrete GPU skus not supported)				13L69AA
HP Desktop Mini 2.5" SATA Drive Bay kit v2	X (125W and discrete GPU skus not supported)				13L70AA
HP Desktop Mini 65W Power Supply Kit	X				L2X04AA
HP Desktop Mini 90W Power Supply Kit	X				L4R65AA
HP Desktop Mini LockBox V2	X (125W and discrete GPU skus not supported)				3EJ57AA
HP Desktop Mini DVD-Writer ODD Expansion Module	X (Either one)				K9Q83AA
HP Desktop Mini I/O Expansion Module					K9Q84AA
HP Desktop Mini Security/Dual VESA Sleeve v3	X (125W and discrete GPU skus not supported)				13L67AA
HP Desktop Mini Security/Dual VESA Sleeve v3 with Power Supply Holder	X (125W and discrete GPU skus not supported)				13L68AA
HP B250 PC Mounting Bracket	X				8RA46AA
HP B300 PC Mounting Bracket	X				2DW53AA
HP B300 PC Mounting Bracket with Power Supply Holder	X (Discrete GPU skus and 150W/180W adapter not supported)				7DB37AA
HP B500 PC Mounting Bracket	X				2DW52AA
HP Desktop Mini Vertical Chassis Stand	X				G1K23AA
HP DM Power Supply Holder Kit v2	X (Discrete GPU skus and 150W/180W adapter not supported)				7DB38AA
HP 150W Elite Mini EPS Holder*	X				657R3AA

Technical Specifications – After Market Options

HP Quick Release Bracket 2	X			X (required pre-configured VESA adapter)	6KD15AA
HP Single Monitor Arm	X			X	BT861AA

NOTE*: Compatible with HP B300 PC Mounting Bracket (2DW53AA) and HP Desktop Mini Security Dual/VESA Sleeve v3 (13L67AA).

Data Storage Drives	DM	SFF	TWR	AiO	Part Number
HP PCIe NVME TLC 256GB SSD M.2 Drive	X	X	X	X	1CA51AA
HP PCIe NVME TLC 512GB SSD M.2 Drive	X	X	X	X	X8U75AA
HP 500GB 7200PRM SATA 3.5" Hard Drive		X	X		QK554AA
HP 1TB 7200rpm SATA 3.5" Hard Drive		X	X		QK555AA
HP SFF SATA DVD-Writer ODD		X			52D76AA
HP TWR SATA DVD-Writer ODD			X		52D77AA

Input Devices	DM	SFF	TWR	AiO	Part Number
HP Desktop Wired 320K Keyboard	X	X	X	X	9SR37AA
HP Desktop Wired 320M Mouse	X	X	X	X	9VA80AA
HP Desktop Wired 320MK Mouse and Keyboard	X	X	X	X	9SR36AA
HP USB Antimicrobial Business Slim Keyboard and Mouse	X	X	X	X	Z9H50AA
HP USB Business Slim CCID SmartCard Keyboard	X	X	X	X	Z9H48AA
HP USB Keyboard	X	X	X	X	QY776AA
HP USB Keyboard and Mouse Healthcare Edition	X	X	X	X	1VD81AA
HP USB Premium Keyboard	X	X	X	X	Z9N40AA
HP USB PS/2 Washable Keyboard & Mouse	X	X	X	X	BU207AA
HP Wireless Business Slim Keyboard and Mouse	X	X	X	X	N3R88AA
HP Wireless Premium Keyboard	X	X	X	X	Z9N41AA
HP PS/2 Business Slim Keyboard		X	X		N3R86AA
HP USB Fingerprint Mouse	X	X	X	X	4TS44AA
HP USB Premium Mouse	X	X	X	X	1JR32AA
HP PS/2 Mouse		X	X		QY775AA
HP Wireless Premium Mouse	X	X	X	X	1JR31AA
HP USB 1000dpi Laser Mouse	X	X	X	X	QY778AA
HP USB Optical Mouse	X	X	X	X	QY777AA
HP USB Hardened Mouse ¹	X	X	X	X	P1N77AA

1. Not available in all regions

Technical Specifications – After Market Options

System Memory	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP 32GB DDR4-2666 DIMM		X	X		1C918AA
HP 32GB DDR4-2666 SODIMM	X			X	1C919AA
HP 4GB DDR4-3200 UDIMM		X	X		13L78AA
HP 8GB DDR4-3200 UDIMM		X	X		13L76AA
HP 16GB DDR4-3200 UDIMM		X	X		13L74AA
HP 32GB DDR4-3200 UDIMM		X	X		13L72AA
HP 4GB DDR4-3200 SODIMM	X			X	13L79AA
HP 8GB DDR4-3200 SODIMM	X			X	13L77AA
HP 16GB DDR4-3200 SODIMM	X			X	13L75AA
HP 32GB DDR4-3200 SODIMM	X			X	13L73AA

Multimedia Devices	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP Business Headset v2	X	X	X	X	T4E61AA
HP S101 Speaker Bar	X	X	X		5UU40AA
HP UC Speaker Phone v2	X	X	X		4VW02AA

Security Devices	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP Business PC Security Lock v3 Kit			X	X	3XJ17AA
HP Dual Head Keyed Cable Lock			X	X	T1A64AA
HP Keyed Cable Lock 10mm	X		X	X	T1A62AA
HP Master Keyed Cable Lock 10mm	X		X	X	T1A63AA
HP Sure Key Cable lock	X				6UW42AA

Stands and Accessories	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP EliteOne 800 G6 23.8" Height Adjustable Stand				X	13L61AA
HP EliteOne 800 G6 23.8" Recline Stand				X	13L62AA
HP EliteOne 800 G6 27" Height Adjustable Stand				X	13L63AA
HP EliteOne 800 G6 27" Recline Stand				X	13L64AA

QuickSpecs

HP EliteDesk 800 G6 and HP EliteOne 800 G6 Business Desktops PCs

Technical Specifications – After Market Options

I/O Devices	DM	SFF	TWR	AiO	Part Number
HP DisplayPort Port Flex IO v2	X	X	X		13L54AA
HP HDMI Port Flex IO v2	X	X	X		13L55AA
HP Type-C® USB 3.1 Gen2 Port Flex IO v2	X	X	X		13L59AA
HP Type-C® USB 3.1 Gen2 Port with PD Flex IO v2	X (Not Available on 512W and discrete GPU SKUs)				13L60AA
HP USB 3.1 Gen1 x2 Module Flex IO v2	X (Not Available on 125W and discrete GPU SKUs)	X	X		13L58AA
HP VGA Port Flex IO v2	X	X	X		13L53AA
HP Serial Port Flex IO v2	X (Not Available on 125W and discrete GPU SKUs)	X	X		13L56AA
HP Serial Port Flex IO 2 v2	X (Not Available on 125W and discrete GPU SKUs)				13L57AA
HP Internal Serial Port (in rear wall)		X	X		3TK82AA
HP PCIe x1 Parallel Port Card		X	X		N1M40AA
HP Serial/PS/2 Adapter Kit (in PCIe slot)		X	X		1VD82AA
HP USB to Serial Port Adapter	X	X	X		J7B60AA
HP USB-C to Display Port Adapter	X	X	X		N9K78AA
HP Single Mini Display Port Adapter to Display Port Adapter	X (Only Available with GPU SKUs)				2MY05AA

NOTE: For more detail on HP I/O Devices please refer to the [HP FLEX IO Option Cards QuickSpecs](#). URL is: <http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06042607>

Communication Devices	DM	SFF	TWR	AiO	Part Number
Intel® Ethernet I210-T1 GbE NIC		X	X		E0X95AA

Intel® Optane Memory	DM	SFF	TWR	AiO	Part Number
512GB Intel® Optane™ Memory H10 with SSD	X	X	X	X	6VF55AA



Change Log

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Date	Version History	Action	Description of Change
July 15, 2020	From v1 to v2	Addition	Supported versions section
July 22, 2020	From v2 to v3	Addition	NVIDIA® GeForce® RTX 2070 Super 8GB GDDR6
August, 2020	From v3 to v4	Addition	DVD-R DL - Up to 6X, DVD+R DL - Up to 6X, DVD-R SL/DL Up to 8X and DVD+R SL/DL Up to 8X on the read/write speed on the blue ray write drive specs on Storage section. Specs for DM environmental section completed. DM rear call outs corrected.
October 6, 2020	From v4 to v5	Correction	ALL-IN-ONE WEIGHTS AND DIMENSIONS tables information.
October 7, 2020	From v5 to v6	Addition	Environmental specs for SFF
October 8, 2020	From v6 to v7	Update	Environmental specs for AiO 24
October 8, 2020	From v6 to v7	Update	Environmental specs for AiO 24
October 27, 2020	From v8 to v9	Correction	Processors footnotes and Turbo boost specs corrected
November 13, 2020	From v9 to v10	Addition	Specification at External Power Supplies row in POWER section
November 20, 2020	From v10 to v11	Correction	Rear components and rear ports call outs section and NVIDIA® GeForce® RTX 2070 Super 8GB GDDR6 specs corrected
November 26, 2020	From v11 to v12	Addition	Environmental specs for TWR
January 6, 2021	From v12 to v13	Update/add	Footnotes added to "At a glance" section and packaging materials data in 23.8-in All-in-One Environmental info updated
January 20, 2021	From v13 to v14	Correction	Intel® i210 10/100/1000 NIC in N&C section corrected
January 21, 2021	From v14 to v15	Removal	HP Thunderbolt 3.0 (4CX35AA) from AMO section
January 26, 2021	From v15 to v16	Correction	System volume for TWR and SFF in Weights and dimensions section
February 17, 2021	From v16 to v17	Correction	"Anti-glare" removed from 27.0" LCD (2560 x 1440) Touch in DISPLAY PANEL SPECIFICATIONS
February 24, 2021	From v17 to v18	Update	At a Glance section Raid bullet and Fiber NIC specification added
March 22, 2021	From v18 to v19	Update	Description added to HP Quick Release Bracket 2 in AMO
April 15, 2021	From v19 to v20	Update/ Correction	Disclaimer for Fiber NIC flex port card added in DM rear call outs/Typo in Power Supply section
April 20, 2021	From v20 to v21	Update	Intel® I219-LM 1 table
May 4, 2021	From v21 to v22	Addition	HP Smart Support and footnote added to software section
May 12, 2021	From v22 to v23	Removal	DM from HP Reverb VR Headset bullet in At a Glance section
June 9, 2021	From v23 to v24	Update	Audio/multimedia settings and call outs except for AiO's
July 2, 2021	From v24 to v25	Addition	10 new processors
July 6, 2021	From v25 to v26	Update	256GB Intel® PCIe® NVMe™ QLC + 16GB Intel® Optane from 32GB
August 6, 2021	From v26 to v27	Update	System memory in AMO updated
August 19, 2021	From v27 to v28	Update	Environmental,Weights and dimensions, Power, Miscellaneous features, display specifications and Storage updated.
November 4, 2021	From v28 to v29	Update	1CA52AA removed and replaced with 52D76AA and 52D77AA added in Data Storage Drives at Amo section.

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December 3, 2021	From v29 to v30	Update	Memory main table module updated Windows 11 upgrade added
March 28, 2022	From v30 to v31	Update	Front / Rear facing 5MP Webcam correction in call outs section
April 28, 2022	From v31 to v32	Correction	Slots for AiO corrected.
June 16, 2022	From v32 to v33	Update	Environmental tables certifications updated
July 26, 2022	From v33 to v34	Update	At a glance section updated
August 11, 2022	From v34 to v35	Update	AMO section DM processors updated to 125W from 95W
October 11, 2022	From v35 to v36	Update	Chassis and System volume specs updated in Weights and dimensions section for TWR
October 27, 2022	From v36 to v37	Addition	HP 150W Elite Mini EPS Holder and note added to DM accessories table / description updated for 7DB38AA and 7DB37AA in AMO section.
December 14, 2022	From v37 to v38	Update	Operative system updated
March 9, 2023	From v38 to v39	Addition	“wireless card” Added to wireless card in the end of module description in Networking and communication section
April 11, 2023	From v39 to v40	Correction	Internal M.2 SSD storage 2242 corrected to 2230 in call outs and ports sections